

IND83207 B0

indie's highly integrated, microcontroller-based, ultrasonic parking assist ASSP

31st January 2022

v1.1

Datasheet



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iND83207 documentation

Contents:

1 Revision History

Rev #	Date	Ву	Description
1.1	31 Jan 2022	МТ	Release for PPAP, including updated package outline drawing for dual source packaging house
1.0	01 Sep 2021	МТ	Release for PPAP, including diagram of device orientation in tape & reel packaging
0.9	04 May 2021	MT	Corrected USTRX FIFO description from little to big endian
0.8	23 Feb 2021	МТ	Minor formatting update
0.7	17 Feb 2021	МТ	Added appendix for errata
0.6	05 Feb 2021	МТ	Updated block diagram and register map
0.5	04 Jan 2021	МТ	Pinout updated
0.4	07 Dec 2020	МТ	Range updated
0.3	09 Sep 2020	MT	Interrupt table added
0.2	21 Aug 2020	МТ	Range updated following testing
0.1	17 Aug 2020	МТ	First release for B0

Ultrasonic Park Assist ASIC

2 iND83207 System Overview

CPU Architecture:

- ARM Cortex-M0 processor running at 16MHz
- System Tick Timer (SysTick 24 bits, interruptible)
- Standard SWD Serial Wire Debugger
- Built-in Nested Vectored Interrupt Controller (NVIC)
- Programmable Watch-Dog Timer

Memory:

- 64kBytes of FLASH Memory (Includes data area software definable by customer)
- 16kBytes of SRAM

Features:

• Integrated power management with direct connect to +12V car battery

Two regulated current drivers for driving the primary side of a center-tapped transformer, with the secondary side connected
to an ultrasonic transducer. Capable of 30kHz to 70kHz burst frequencies with programmable current level and
programmable burst length

- Low noise ultrasound receiver with programmable gain
 - o Digital signal processing with integrated digital filtering
 - One Master and one Slave LIN 2.2 controllers
 - Two LIN pins, each can be configured to operate as
 - · LIN master or LIN slave
- firmware-controlled GPIO
- · LIN input/output function can mux between LIN controller, PWM, or firmware-controlled GPIO
- Five 3.3V-level GPIOs with analog input support to housekeeping ADC
- Three VBAT-level GPIOs with analog input support to housekeeping ADC
- Integrated junction temperature sensor
- Integrated high-accuracy calibrated reference oscillator for accurate time measurement using a frequency counter function
- Integrated one-time programmable (OTP) memory for unique device traceability

Quality / Reliability compliance to:

- AEC-Q100 Grade 2 Qualified (Operating Ambient Temperature range -40C to +105C)
- LIN Specification Package 2.2A and J2602-1 Nov 2012 and J2602-2 Nov 2005
- ISO 17987 (2016): Road Vehicles Local Interconnect Network (LIN)
- Compliant to all major environmental regulations (RoHS, Sony Green, Conflict Free)

Package:

• 24-pin QFN 4x4mm with exposed pad

2.1 Application Description

iND83207 provides a completely integrated solution for high performance ultrasonic automotive parking assist applications. iND83207 integrates a powerful 32-bit ARM M0 with 64kB of FLASH and 16kB of SRAM. A portion of the FLASH integrates proprietary DSP algorithms which eases the hardware requirements of the devices and lowers overall system cost.

iND83207 also includes an integrated power management block (PMU) directly connected to the car battery, from which all the supplies required by the ASIC are generated. iND83207 integrates two regulated current drivers for driving the primary side of a center-tapped transformer, with the secondary side connected to an ultrasonic transducer. The driving frequency and number of pulses can be accurately programmed to match the transducer resonant frequency and the application requirements. iND83207 also enables the measurement of transducer reverberation so that the resonant frequency can be accurately measured, and the driving frequency tuned to match, for maximum power transfer.

Sensing of objects is performed by receiving the reflected echo signals via the ultrasonic transducer. The received echo is amplified with a high precision analog front end which includes a low noise amplifier (LNA) followed some stages of programmable gain amplifiers (PGAs) and the signal is then fed into an ADC. Digital signal processing (DSP) of the signals follows the ADC and the output of this DSP can be captured into microcontroller memory. Echo detection and association algorithms are implemented in firmware.

Additionally, the IC integrates a LIN master controller, a LIN slave controller and associated transceivers. The two LIN pins can operate as LIN transceivers, or can be used as high-voltage GPIOs. There are three additional high-voltage (VBAT-level) GPIOs which can provide 10mA of current source capability.

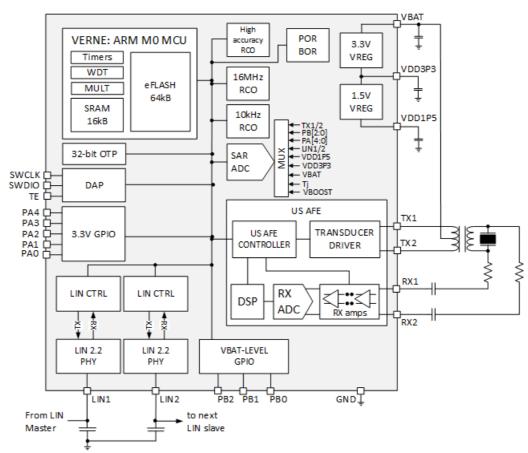
31st January 2022

Five 3.3V-level GPIOs are provided for any requirements the customer wants to add, such as some methods of slave node addressing.

An 8-bit housekeeping ADC allows firmware to monitor all supply voltages, a temperature sensor, the LIN1/2 pins, the PA[4:0] pins and the PB[2:0] pins. This enables system diagnostics to be performed.

2.2 Functional Diagram

The figure below shows the block diagram of the IC where the entire ultrasonic parking assist application is created with an external transducer and transformer and a few passive components.



iND83207 block diagram

2.3 Pin Description

..table:: Pin List

	I	I	I	I	Datasneet -
Pin number	Pin Name	Туре	Voltage	Direction	Description
23	VBAT	Supply	VBAT	Input	Battery supply input
6	VDD3P3	Supply	VDD3P3	I/O	3.3V regulator decoupling capacitor
16	VDD1P5	Supply	VDD1P5	I/O	1.5V regulator decoupling capacitor
1	TX1	Analog	VBAT	I/O	Ultrasonic transducer driver pin 1
2	TX2	Analog	VBAT	I/O	Ultrasonic transducer driver pin 2
4	RX1	Analog	VDD3P3	Input	Ultrasound receiver pin 1
5	RX2	Analog	VDD3P3	Input	Ultrasound receiver pin 2
19	LIN1	Analog	VBAT	I/O	LIN1 Pin
18	LIN2	Analog	VBAT	I/O	LIN2 Pin
11	PA0	3V3IO	VDD3P3	I/O	General purpose IO
10	PA1	3V3IO	VDD3P3	I/O	General purpose IO
9	PA2	3V3IO	VDD3P3	I/O	General purpose IO
8	PA3	3V3IO	VDD3P3	I/O	General purpose IO
7	PA4	3V3IO	VDD3P3	I/O	General purpose IO
22	PB0	HVIO	VBAT	I/O	General purpose HV IO
21	PB1	HVIO	VBAT	I/O	General purpose HV IO
20	PB2	HVIO	VBAT	I/O	General purpose HV IO
3	TE	3V3IO	VDD3P3	I/O	Test enable
14	SWDIO	3V3IO	VDD3P3	I/O	Debugger data
13	SWCLK	3V3IO	VDD3P3	Input	Debugger clock
15	PROG	Supply	•	I/O	Programming power supply for fuses, engineering samples only
EP	GND	Ground			Exposed pad
12	NC				No Connect
17	NC				No Connect
24	NC				No Connect

Pin state upon power-on reset:

• Unless otherwise noted, all pins default to tristate/Isolation mode (Hi-Z) upon power-on reset.

3 Electrical Specifications

3.1 Absolute Maximum Ratings (AMR)

			Dalas	11000
Parameter	Conditions	Min.	Max.	Unit
VBAT	Up to 500ms	-0.3	45	٧
VBAT	ISO 7637-2 pulse 1, VBAT=13.5V, TA=23°+/-5C, test pulse applied to VBAT via reverse polarity diode and more than 1uF capacitor	100		V
VBAT	ISO 7637-2 pulse 2 VBAT=13.5V, TA=23°+/-5C, test pulse applied to VBAT via reverse polarity diode and more than 1uF capacitor		75	٧
VBAT	ISO 7637-2 pulses 3A, 3B, VBAT=13.5V, TA=(23+/-5)°C, test pulse applied to VBAT via reverse polarity diode and more than 1uF capacitor	- 150	100	٧
VBAT	ISO 7637-2 pulses 5b VBAT=13.5V, TA=(23+/-5)°C, test pulse applied to VBAT via reverse polarity diode and more than 1uF capacitor		45	V
LIN1, LIN2	Up to 500ms. Note that the negative end of the LIN voltage spec is applicable only when the GND is lost.	-40	40	V
LIN1, LIN2	ISO 7637-2 pulse 1, VBAT=13.5V, TA=23°+/-5C, test pulse applied to LIN via 1nF capacitor	- 100		V
LIN1, LIN2	ISO 7637-2 pulse 2, VBAT=13.5V, TA=23°+/-5C, test pulse applied via 1nF capacitor		75	V
LIN1, LIN2	ISO 7637-2 pulses 3A, 3B, VBAT=13.5V, TA=(23+/-5)°C, test pulse applied via 1nF capacitor	- 150	100	V
VDD3P3		-0.3	3.6	V
TX1, TX2	Up to 500ms	-0.3	45	V
PA[4:0], SWCLK, SWDIO, RX1, RX2		-0.3	3.6	٧
PB[2:0]	Up to 500ms	-0.3	VBAT+0.3	V
Ambient Temperature		-40	105	°C
Junction Temperature		-40	125	°C
Storage Temperature		-55	150	°C

3.2 Reliability (ESD and Latch Up)

Parameter	Conditions	min	max	unit
All pins	HBM, JEDEC/ AEC-Q100 Conditions	-2	+2	kV
All Pins	CDM, JEDEC/ AEC-Q100 Conditions	- 500	+500	V
All pins	Latchup, JEDEC JESD78 Level A	100	+100	mA

3.3 EMC Information

The target of the iND83207 product is to minimize the external components required to meet the required EMC specifications. Final recommendations on board layout will be provided to the customer to minimize the need for external components.

3.4 Electrical Characteristics

Electrical Characteristics are valid over the full junction temperature range of Tj = -40°C to +125°C and a supply range of $7V \le VBAT \le 18V$, with typical values quoted for VBAT=12V, unless otherwise noted.

Parameter	Conditions	min	typ	max	unit
VBAT Input Voltage	No damage to sensor			30	V

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Parameter	Conditions	min	typ	max	unit
VDD3P3 Output Voltage	Across full output load range	3.0	3.3	3.6	V
Current Consumption	MCU on, US TX and RX active,		10	17.5	mA
Recommended VDD3P3 decoupling capacitor			1		μF
Clocks					
System RC oscillator (HFRC) frequency		15.2	16	16.8	MHz
Reference oscillator			550		kHz
Auxiliary RC Oscillator (LFRC) frequency		3.5	10	16.5	kHz
POR/BORs					
POR (VDD3P3)	Voltage below which ASIC is reset		1.55	1.75	V
BOR (VDD3P3)	Voltage below which ASIC operation is halted	2.3	2.4		V
BOR (VDD1P5)	Voltage below which ASIC operation is halted	1.28	1.35		V
Junction Temperature Sensor					
Temperature range		-40		125	°C
Temperature Accuracy		-10		+10	°C
Ultrasound system					
Distance detection range		0.2		2.0	m
Distance detection accuracy			1		cm
Transducer Driver pins TX1 / TX2					
Driver frequency range, Fdrv	Guaranteed by design	40		70	kHz
Driver Current at min code	V(TXx)=6V, IDRV code=0, inferred ATE measure	175	200	225	mA
Driver Current at max code	V(TXx)=6V, IDRV code=31, inferred ATE measure	395	450	505	mA
Current Adjustment Steps			8.1		mA
Leakage Current	V(TXx)=VBAT, Tj=105°C max	-1		1	μА
Driver Voltage Drop	Output current drops by less than 20%, code=0. Guaranteed by initial characterization.		0.6	1.2	V
Number of drive periods in a burst		1		64	
Receiver pins RX1 / RX2					
Minimum Gain	Fdrv = 51.2kHz. Setting AFE_gain[4] at room temperature	44	52	61	dB
Maximum Gain	Fdrv = 51.2kHz. Setting AFE_gain[11] at room temperature	78	88	98	dB
Analog gain change from calibrated value	Fdrv = 51.2kHz. Using RX gain compensation in FW for temperature. Settings from AFE_gain[5] to AFE_gain[10]	-2		2	dB
Gain step size	Gain adjustment is implemented using coarse steps in the analog part of the receiver and fine steps using digital adjustment in FW			0.1	dB

Parameter	Conditions	min	typ	max	unit
Input Impedance	Code 0 Code 1 Code 2 Code 4		525 130 86.5 16.7		kΩ kΩ kΩ kΩ
Input-referred noise	@ 51.2kHz, at final output from DSP filtering. Guaranteed by design.		5	9	nV/(Hz) ^{1/}
Reverb frequency measurement accuracy	Reverb frequency measurement is achieved by measuring many individual cycles of the reverberation signal and accuracy is assured by firmware.	-200		200	Hz
8-bit SAR ADC					
Conversion rate	Guaranteed by design			200	ks/s
INL	Slowest selectable conversion rate	-1		1	LSB
DNL	Slowest selectable conversion rate	-1		1	LSB
VDD3P3-level GPIOs, PA[4:0]					
Input voltage for logic low				0.3* VDD3P3	V
Input voltage for logic high		0.7* VDD3P3			V
Logic low output level	Iol=-5mA			0.4	٧
Logic high output level	Ioh=5mA. Current is supplied from VDD3P3.	2.4			V
Pull-down resistance			10		kΩ
Pull-up resistance			10		kΩ
VBAT-level GPIOs, PB[2:0]					
Input voltage for logic low				0.8	٧
Input voltage for logic high		2			V
Strong pull-down current			5		mA
Strong pull-up current			-10		mA
Weak pull-down current			100		μΑ
Weak pull-up current			- 100		μΑ
LIN1, LIN2 – refer to LIN 2.2 specification, VBUS=LIN pin					
IBUS_LIM	Current limitation for driver dominant state driver on VBUS = VBAT_max=18V	40		200	mA
Rslave	LIN configured as a slave	20	30	60	kΩ
Rmaster	LIN configured as a master	0.75	1	1.25	kΩ
IBUS_PAS_dom	Input Leakage Current at the Receiver including Pull-Up Resistor driver off VBUS = 0V VBAT= 12V	-1			mA
IBUS_PAS_rec	Driver off, VBUS>VBAT 8V <vbat<16v 8V<vbus<16v< td=""><td></td><td></td><td>20</td><td>μΑ</td></vbus<16v<></vbat<16v 			20	μΑ
Device Bus Leakage Current Ground Disconnected	VBAT= VGND=12V, 0V <vbus<18v J2602</vbus<18v 	-100		100	μΑ
Device Bus Leakage current VBAT disconnected	0V <vbus<18v, vbat="VGND=0V</td"><td>-23</td><td></td><td>23</td><td>μΑ</td></vbus<18v,>	-23		23	μΑ

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Parameter	Conditions	min	typ	max	unit
BUS_VOH Transmitter dominant voltage	Load 500Ohms, driver open drain active	0.8		1.0	VSUP
BUS_VOL Transmitter recessive voltage	Driver open drain high impedance	0.0		0.2	VSUP
LIN pin input capacitance	Note that LIN 2.2A spec 220pF typ, 250pF max as total node capacitance at the connector including the physical bus driver and all other components including C _{LIN}			20	pF
VBUSdom	Receiver dominant state			0.4	VSUP
VBUSrec	Receiver recessive state	0.6			VSUP
VBUS_CNT	Center point Receiver VBUS_CNT = (Vth_dom+ Vth_rec)/2	0.475	0.5	0.525	VSUP
Vhys	Receiver hysteresis VHYS = Vth_rec -Vth_dom	0.075		0.175	VSUP
Trx_pd	propagation delay of receiver. Guaranteed by initial characterization. C _{RXD} load 20pF (RX output of transceiver, internal node, access in test mode) minimum slew rate for the LIN rising and falling edges is 50V/µs			6	μς
Trx_sym	symmetry of receiver propagation delay. Guaranteed by initial characterization. rising edge w.r.t. falling edge C _{RXD} load 20pF C _{RXD} load 20pF (RX output of transceiver, internal node, access in test mode)	-2		+2	μѕ
LIN1, LIN2 Timing parameters (CBUS; RBUS): $(1nF; 1k\Omega/(6.8nF;660\Omega/(10nF;500\Omega))$	Guaranteed by initial characterization.				
D1 Duty Cycle (20kbits/s)	$THRec(max) = 0.744 \times VSUP; \\ THDom(max) = 0.581 \times VSUP; \\ VSUP = 7.0V16V; tBit = 50 \mu s; \\ D1 = tBus_rec(min) / (2 \times tBit)$	0.396			
D2 Duty Cycle (20kbits/s)	$THRec(min) = 0.422 \times VSUP; \\ THDom(min) = 0.284 \times VSUP; \\ VSUP = 7.6V16V; tBit = 50 \mu s; \\ D2 = tBus_rec(max) / (2 \times tBit)$			0.581	
D3 Duty Cycle (10.4kbits/s)	$THRec(max) = 0.778 \times VSUP; \\ THDom(max) = 0.616 \times VSUP; \\ VSUP = 7.0V16V; tBit = 96 \mu s; \\ D3 = tBus_rec(min) / (2 x tBit)$	0.417			
D4 Duty Cycle (10.4kbits/s)	$THRec(min) = 0.389 \times VSUP; \\ THDom(min) = 0.251 \times VSUP; \\ VSUP = 7.6V16V; tBit = 96\mu s; \\ D4 = tBus_rec(max) / (2 \times tBit)$			0.590	
tBus_rec(min)- tBus_dom(min)	$\Delta t3$, 10.4kbs operation, low speed mode			15.9	μs
tBus_rec(min)- tBus_dom(max)	Δ t4, 10.4kbs operation, low speed mode			17.28	μs
Piezo speaker driver function on LIN1/2					
Current output	Code 0, V _{LIN} =3.5V Code 1, V _{LIN} =3.5V Code 2, V _{LIN} =3.5V Code 3, V _{LIN} =7V	20	10 20 40 80	60	mA mA mA
Drive modulated frequency	PWM with duty from 0.2 to 0.8	0.5		3.5	kHz
LIN1 / LIN2 high-speed mode					

Parameter	Conditions	min	typ	max	unit
Baud rate	VBAT=12.0V, external pull-up resistor 220Ω to VBAT, T_A =20C-30C, $C_{LIN} < 4$ nF This mode will use the UART controller instead of the LIN master or slave controllers.			62	kbaud

4 Device Functional Description

4.1 Ultrasound analog front-end

iND83207 makes use of ultrasonic distance measuring principles by transmitting a pulse and then measuring the time it takes to receive the reflected or echo, pulse back at the transducer. The physical relationship between the distance from the transducer to the object of interest is given by distance X = (c * t) / 2, where c is the speed of sound in air (c = 343 m/s at 20°C) and t is the time it takes for a transmitted pulse to return back to the transducer.

4.1.1 Transducer Driver and Burst Generation

The drive patterns are produced by the ultrasound AFE controller. A transmit cycle is of programmable length from 1 to 64 cycles with accurate frequency control.

The ultrasound transducer is driven through a transformer. The primary side of the transformer has a centre-tap connected to VBAT, and iND83207 drives the two ends alternately with current-controlled pull-downs. The drive current strength is controllable through user registers.

4.1.2 Ultrasound Receiver

The signal at the transducer is AC coupled to iND83207 via a series resistor and capacitor from both sides of the transducer, as shown in the block diagram in Figure 1.

At the receiver, the differentially sensed signal goes through a series of amplifiers with programmable gain followed by an ADC. After digitization, the signal is processed by a series of digital filter operations. The final output from the filters is a stream of numbers which indicate the level of signal at the transducer resonant frequency. This "envelope" data will be available to the microcontroller at a time resolution which enables the time of flight to be calculated to the required accuracy.

The iND83207 receiver will be designed for the given noise target, where this will include all external components. Another target for the iND83207 design is to significantly reduce the harmonic component of the input signal in the final output envelope data (this is an improvement relative to the original Qin design).

The implementation of the receive chain is shown below.

./images/USRX_diagram.png

US Rx Diagram

Receiver input offset cancellation

Voltage offset at the receiver input is automatically cancelled by iND83207.

Receiver gain control

The receiver gain can set by firmware writing to a specific control register. The gain may be fixed for the full length of an envelope capture. Alternatively, firmware can adjust the gain throughout the envelope capture period.

The LNA and four amplifiers are cascaded to generate the receiver gain as shown in US Rx Diagram. LNA gain is defined by PMOS based gm with a resistive load. The following stages, PGA1/PGA2 gain is calculated by PMOS based resitive load gm with a constant gm current bias. The last two stages (PGA3/PGA4) gain is simply the ratio of the feedback resistor divided-by the input resistor. PGA3 and PGA4 are NMOS differential OP Amp with resitive feedback for linearity. There is an option to bypass PGA1 and PGA2 for a lower RX gain.

Dynamic gain control (DGC)

Dynamic adjustment of gain in the receiver is supported through hardware which adjusts the signal gain. The user controls both gain levels and points in time where the change is applied.

The gain adjustment may be applied either to the gain through the RX amplifier chain, or through the gain control in the DSP.

This function enables the user to increase the gain as the time from transmission increases, so that the gain is higher when the expected echo signal is smaller.

Dynamic gain control will be combined with dynamic adjustment of the thresholds in the echo detection algorithm to optimize the system.

4.1.3 Echo detection and echo association

The envelope data will be read from the DSP in system RAM for processing which will normally be done after the full envelope has been captured.

Echo detection and echo association algorithms of any form can be implemented in firmware.

4.1.4 Transducer reverb frequency measurement

Measurement of the resonant frequency of the transducer is vital for proper functioning of the system. The system uses this information to adjust the driving frequency (to maximize the output power).

iND83207 will enable the measurement of the transducer reverb frequency at the end of any drive phase when active damping is not in operation. The ability to measure this feature has been demonstrated in Qin A1 to work very accurately using a firmware-based method.

iND83207 will implement a hardware method which will give the same accuracy as is demonstrated on Qin A1. This will enable the gathering of a sequence of measurements of the individual reverberation periods and will use the micro-controller block-transfer engine (BTE) to transfer these from the ASIC die to SRAM on the micro-controller die. Firmware needs only to set this up, it is not involved as the data is captured to SRAM. At the end of the reverberation period, firmware can read all the captured data and calculate the reverberation frequency from that data.

Experimentation with Qin A1 has shown that the reverberation frequency is not static immediately after the end of the transmit period. It has been shown that the reverberation frequency in the first few cycles can be in error by more than 2kHz, and that it can take 8 cycles before this frequency settles to within 200Hz of the natural frequency. The proposed solution gives the ability to measure as many cycles of the reverberation frequency as desired, and firmware can analyze the results to accurately estimate the reverberation frequency.

4.1.5 Transducer reverb duration measurement

The transducer reverb duration may be used as a diagnostic measure of the health of the transducer. This duration can be measured from the envelope data captured on any transmit

phase, using firmware to measure when the energy at the resonant frequency falls below a threshold.

5 Cortex-M0 Processor Subsystem

The iND83207 SiP includes an embedded microcontroller subsystem based upon the ARM Cortex M0 core. This processor includes a 64 kByte program flash memory and 16 kByte SRAM. It also includes three general-purpose 32-bit timers plus a dedicated watchdog timer. Additionally, it includes a Nested Vector Interrupt Controller (NVIC) to schedule hardware interrupts. The ARM Cortex M0 implementation supports 8-bit, 16-bit, and 32-bit reads/writes to peripherals.

Memory Map Summary

Address range	Memory	Description
0x00000000 - 0x0000FFFF	Flash	64 Kbytes of Flash Memory, user programmable
0x00010000 - 0x000101FF	Flash NVR 1	512 bytes of the NVR 1 sector
0x00010200 - 0x000103FF	Flash NVR 2	512 bytes of the NVR 2 sector
0x00010400 - 0x000105FF	Flash NVR 3	512 bytes of the NVR 3 sector
0x00010600 - 0x000107FF	Flash NVR 4	512 bytes of the NVR 4 sector
0x00010800 - 0x000109FF	Flash NVR 5	512 bytes of the NVR 5 sector
0x00010A00 - 0x1FFFFFF	N/A	Reserved
0x20000000 - 0x20003FFF	SRAM	16 Kbytes of SRAM
0x20004000 - 0x4FFFFFF	N/A	Reserved
0x50000000 - 0x5000007F	ASIC Peripherals	128 Byte peripheral fast access
0x50000080 - 0x5000FFFF	MCU Peripherals	Block Transfer Engine
0x50010000 - 0x5001FFFF	ASIC Peripherals	64 Kbyte peripheral slow access
0x50020000 - 0x5002001F	MCU Peripherals	General Purpose Timers Controls
0x50020020 - 0x500200FF	Flash	Flash Programming/Erase Control
0x50020100 - 0xDFFFFFF	N/A	Reserved
0xE0000000 - 0xE00FFFFF	Private Peripheral Bus	ARM peripherals
0xE0100000 - 0xEFFFFFF	N/A	Reserved
0xF0000000 - 0xF0001FFF	System ROM tables	ARM core IDs
0xF0002000 - 0xFFFFFFF	N/A	Reserved

5.1 ARM M0 Processor "Verne" Specification:

2 System Overview

2.1 ARM Architecture

- ARM Cortex-M0 processor
- System Tick Timer (SysTick 24 bits, interruptible)
- Serial Wire Debugger (2 pins)
- Built-in Nested Vectored Interrupt Controller (NVIC)
- Four Breakpoints and two Watch points

2.2 Additional Features

- Programmable Watch-Dog Timer (Trigger time: 213, 219, 222, and 232 clock cycles)
- Three General Purpose 32-bit Timers

2.3 Memory

- 64kB of Flash Program Memory (16kx32) operating at a maximum MCU freq. No Cache.
- 16kB of SRAM split into two 8KB macro (x32)

2.4 Speed

- 30MHz maximum CPU frequency with no flash read wait state
- MCU-ASIC bus frequency operates at the same speed than CPU

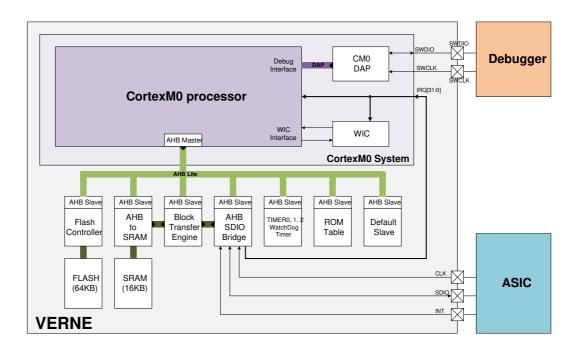
2.5 Operating Junction Temperature

• -40 °C to +125 °C

2.6 Power Use cases

- Power Off
- Idle/standby (WFI), driven by ASIC (hold the clock). Flash in standby mode.
- Active

2.7 Top Level Block Diagram



3 Memory Description and map

ARM Cortex M0 uses a unified memory model with a linear address space (Von Neumann architecture) including Flash and RAM memories as well as registers address space. The indie implementation of the Cortex M0 core uses a high density 64KB Flash cell along with 16KB of SRAM. The following table defines the several regions of the address space:

Memory map

Address range	Memory	Description
0x00000000 - 0x0000FFFF	Flash	64 Kbytes of Flash Memory, user programmable
0x00010000 - 0x000101FF	Flash NVR 1	512 bytes of the NVR 1 sector. [for internal Indie use only]
0x00010200 - 0x000103FF	Flash NVR 2	512 bytes of the NVR 2 sector. [for internal Indie use only]
0x00010400 - 0x000105FF	Flash NVR 3	512 bytes of the NVR 3 sector. [for internal Indie use only]
0x00010600 - 0x000107FF	Flash NVR 4	512 bytes of the NVR 4 sector. [for internal Indie use only]
0x00010800 - 0x000109FF	Flash NVR 5	512 bytes of the NVR 5 sector. [for internal Indie use only]
0x00010A00 - 0x1FFFFFFF	N/A	Reserved
0x20000000 - 0x20003FFF	SRAM	16 Kbytes of SRAM
0x20004000 - 0x4FFFFFF	N/A	Reserved
0x50000000 - 0x5000007F	ASIC Peripherals	(Implementation Dependent)
0x50000080 - 0x5000FFFF	MCU Peripherals	Block Transfer Engine
0x50010000 - 0x5001FFFF	ASIC Peripherals	(Implementation Dependent)
0x50020000 - 0x5002001F	MCU Peripherals	General Purpose Timers Controls
0x50020020 - 0x500200FF	Flash	Flash Programming/Erase Control
0x50020100 - 0xDFFFFFF	N/A	Reserved
0xE0000000 - 0xE00FFFFF	Private peripheral bus	ARM peripherals
0xE0100000 - 0xEFFFFFFF	N/A	Reserved
0xF0000000 - 0xF0001FFF	System ROM tables	ARM core IDs
0xF0002000 - 0xFFFFFFFF	N/A	Reserved

3.1 System Memory (SRAM)

MCU core implements 16kbytes of SRAM. MCU can execute codes from the SRAM memories. The SRAM macros can be put in retained state into which the supply is maintained and clock source stopped (idle). The design does not support power switch to cut off supply on non-active logic in such state and "put the burden" on the ASIC side to optimize power consumption including lowering the supply voltage without SRAM and other FF data losses.

3.2 Flash Non Volatile Memory

MCU implements a Programmable Flash Memory with x32 configuration, sector and chip erase and byte program capability. It integrates five 512bytes nonvolatile registers (NVR) sectors which are only for internal Indie use.

In normal operation the ARM core fetches instructions (or data permanently stored) from the Flash memory but it is also possible for a program to alter the content of the flash memory. The following operations can be performed in the Flash Memory:

- Byte Write
- Sector Erase
- Code Protect

For a description of the flash memory registers, please refer to the product register map. Here is a simple description of the basic features supported:

- Registers support to write/erase data to a byte, sector address
- Support programmable read wait states (The design is implemented such that the timings associated with the flash macro meet the maximum speed of the system clock requirements)
- Support system clock divider for write/erase functions
- · Protection mechanism to unlock flash memory write and start flash memory byte-write
- Protection mechanism to unlock flash memory sector erase

The flash macro is 32-bit wide but the write can be done on 8-bit. 16-bit or the full 32-bit.

4 Reset

The system can be reset through the following events:

- power on reset. When the 1.5V power supply gets sensed and reach a specific threshold, a POR cell will release the reset few micro second after the 1.5V is stable.
- The POR circuit also monitors the IO voltage and it can trigger a reset if this voltage gets to a lower value than the nominal
 3.3V. There is a configuration bit in the first NVR of the flash (bit 17) which will mask this reset. If this bit is set to high, the
 ASIC can disconnect the IO supply to save power without triggering a reset. This feature can be used when the processor is in
 Deep Sleep mode.

• Note

There is no specific hardware to sequence the events in order to remove the IO supply. This needs to be done based on time since the removal of this IO supply will cut the communication between the processor and the ASIC.

- assertion of the RST_N pin. This pin may not be available for all the application (legacy chips do not have this pin). This pin has an internal pull-up. The reset is active low.
- System reset request of the Cortex-M0 system through the Debugger
- The ASIC can request a system reset through the Interrupt interface (code=0x1C). This is implementation dependent. All ASIC
 do not have this feature implemented. Check the specification of the ASIC for more information.

5 Interrupt

5.1 Interrupt Vector

The first 148 bytes of Flash Memory are organized following the standard created by ARM. In this standard the Address 0x00000 contains the top-of-stack address (four bytes). The following addresses contain interrupt vectors used by the microcontroller:

Interrupt Vector

Vector Name	Address	Comments
STACK_VALUE	0x00000	Typically set to 0x20000FFFF (Top of SRAM)

Vector Name	Address	Comments
Reset_Handler	0x00004	
Reserved	0x00008	
HardFault Handler	0x0000C	
Reserved	0x00010 to 0x00028	
SVC_Handler	0x0002C	
Reserved	0x00030 and 0x00034	
PendSV_Handler	0x00038	
SysTick_Handler	0x0003C	
Dependent on product implementation	0x00040 to 0x0007C	
Timer0_Handler	0x00080	
Timer1_Handler	0x00084	
Timer2_Handler	0x00088	
Watchdog_Handler	0x0008C	
BTE_Handler	0x00090	Block Transfer. Contact indie to get more information.
Reserved	0x00094	

All other addresses in the flash memory can be used for the user's program. The meanings of the standard interrupt vectors (Provided with the ARM Cortex M0 core) are defined in ARM's documentation. One of the sources of information is: Cortex-M0 Devices Generic User Guide

5.2 Interrupt Enabling/Disabling Process

Cortex-M0 implements a NVIC (Nested Vector Interrupt Controller) peripheral capable of handling up to 16 peripheral's interrupts. Upon reset the microcontroller can answer only to Reset, NMI (Non-Maskable Interrupt) and Hard-Fault interrupts/exceptions. All other interrupts must be enabled. To enable and disable the interrupts the user must use access the ISER (Interrupt Set Enable Register) and ICER (Interrupt Clear Enable Interrupt) registers associated with the desired interrupt.

Note

Both inline functions and all parameters are defined in the product_file.h file, which must be included in the source files. Besides that the product_file.h file contains a list of available interrupts. The format of this list is as follows:

```
typedef enum IRQn {
NonMaskableInt_IRQn = -14, // Non Maskable Interrupt
HardFault_IRQn
                        = -13, // Hard Fault Interrupt
SVCall_IRQn
                        = -5, // SV Call Interrupt
= -2, // Pend SV Interrupt
PendSV IRQn
                                // System Tick Interrupt
                         = -1,
SysTick_IRQn
//**** CMOIKMCU Cortex-MO specific Interrupt Numbers ***************
IRQ00 IRQn
                         = 0,
                                 // Product specific
IRQ01_IRQn
                         = 1,
                                 // Product specific
                        = 2,
= 3,
                                // Product specific
// Product specific
IRQ02_IRQn
IRQ03_IRQn
                        = 4,
                                // Product specific
IRQ04_IRQn
                                // Product Specific
                        = 5,
IRQ05_IRQn
IRQ06_IRQn
                         = 6,
                                 // Product Specific
                        = 7,
                                 // Product Specific
IRQ07_IRQn
IRQ08_IRQn
                         = 8,
                                // Product Specific
IRQ09_IRQn
                         = 9,
                                 // Product Specific
                        = 10,
                                 // Product Specific
IRQ10 IRQn
                        = 11,
                                 // Product Specific
IRQ11_IRQn
                        = 12,
                                 // Product Specific
IRO12 IROn
                        = 13,
IRQ13_IRQn
                                 // Product Specific
IRQ14_IRQn
                        = 14,
                                 // Product Specific
                                 // Product Specific
IRQ15 IRQn
                        = 15,
TIMER0_IRQn
                         = 16,
                                 // Timer 0
                        = 17,
                                 // Timer 1
TIMER1 IROn
TIMER2_IRQn
                        = 18,
                                 // Timer 2
                        = 19,
                                // Watchdog timer
// Block Transfer Engine
WATCHDOG_IRQn
                        = 20,
BTE_IRQn
                         = 21
SDIO_IRQn
                                 // Serial Data IO
} IRQn_Type;
```

6 Flash

The MCU contains a 64kB flash memory. This memory is configured as a ROM memory in the address space from 0x0000000 to 0x0000FFFF. Since this space includes the boot vector, the microcontroller boots from an address configured in this flash memory, and user code will typically execute from this memory as well. The flash memory is arranged in 512-byte sectors. Memory can be erased one sector at a time, and can be written either one byte, 16-bit or a full 32-bit word at a time. The writing and erasing of memory is handled by a memory-mapped peripheral.

6.1 Flash Read Only Memory

The flash memory is memory mapped into a read-only address range below 0x0000FFFF. These addresses cannot be written to directly. To modify the flash contents, the flash controller peripheral must be used. There are five sectors starting at 0x00010000 which are reserved for AyDeeKay production test use and cannot be written or erased by the user code. Consequentially, the sector starting at 0x00010000 cannot be erased using the sector erase command. All other sectors in this block can still be erased and bytes in these sectors can be written to by the user code.

Flash Memory Map

Starting Address	Ending Address	Description
0x00000000	0x0000FFFF	Read only access FLASH. Each sector can be erased and can be written using flash controller peripheral.
0x00010000	0x000109FF	Read only access FLASH. These sectors cannot be modified and typically contains Indie Semi information written during production test.

6.2 Flash Memory Control

The flash memory can be written and erased using a memory-mapped flash control peripheral. To avoid unintentional modification to the flash memory, an unlocking scheme is implemented which

requires multiple sequential operations in a fixed order in order to erase or write the flash contents. Flash writes complete within 20µs, while sector erase operations can take up to 10ms to complete. The flash cannot be read during a write or erase operation. Since program code typically resides in flash, this will result in the program stalling for the duration of the write / erase operation unless counter-measures are taken. If continued program execution during flash modification is required, then any code which must continue to run should execute from SRAM during the flash write/erase to avoid the processor stalling from attempting to fetch its code from the flash memory. Furthermore, the interrupt vector table is located in flash memory. If an interrupt occurs and it is enabled, then the MCU will attempt to retrieve the interrupt service routine's address from the flash memory. If the flash is busy performing a write or erase when this occurs, the processor will halt until the interrupt vector can be read from the flash. The interrupts numbered 0, 1, 2 and 16 are cached so that the vector fetch will not be stalled by the flash unavailability. So for these interrupts, if the service routine is mapped to a function in SRAM then the interrupt servicing will not stall the MCU during flash modification operations. Other interrupts should be disabled prior to initiating the flash operation if a MCU stall caused by their servicing must be avoided. Disabled interrupts will still pend, so re-enabling them after completion of the flash modification operation will cause any of the disabled interrupts which had occurred to be serviced at that time.

6.3 Flash Memory Operations & Examples

The following operations can be performed in the Flash Memory:

- Sector Erase
- Byte / Half-word / word Program
- Code Protect

Sector Erase

To erase a 512 byte sector the following sequence must be followed:

- 1. Write an address inside the sector to be erased to the ADDR register.
- 2. Unlock the sector for erasure by writing the 0x6666666 pattern to the UNLOCK_ERASE register.
- 3. Start the sector erase process by writing the 0x9999999 pattern to the ERASE_START register.

```
FLASH_SFRS->ADDR = 0x000050A0; //Point to the block starting at 0x00005000 //(any address 0x5000 to 0x50FF will work)

FLASH_SFRS->ERASE_START = 0x99999999; //Start erase process
```

• Note

The erase process of a sector can take up to 10msec.

Write Byte

To write a byte the following sequence must be followed:

- 1. Write the flash address to be programmed to the ADDR register.
- 2. Write the value to be written into the DATA register. (Bits 31 to 8 are ignored) $\,$
- 3. Unlock the write by writing the 0x55555555 pattern to the UNLOCK_WRITE register.
- 4. Start the writing process by writing the 0xAAAAAAA pattern into the WRITE_START register.

```
FLASH_SFRS->ADDR = 0x000050BB; //Point to the byte address

FLASH_SFRS->DATA = 0xAB000000; //Load byte (0xAB) to be written

//Need to align with address

FLASH_SFRS->UNLOCK_WRITE = 0x55555555; //Unlock byte write

FLASH_SFRS->WRITE_START = 0xAAAAAAAA; //Start write process
```

• Note

The byte write process can take up to 20µs.

Write Half-Word (16-bit) or Word (32-bit)

To write a byte the following sequence must be followed:

- 1. Unlock the write to the Control Operation register by writting 0xACDC_1972 in the UNLOCK_CTRL_OP register.
- 2. Configure the size of the write in the CTRL_OP.SIZE register. Refer to table below to define the correct value.
- 3. Write the flash address to be programmed to the ADDR register.
- 4. Write the value to be written into the DATA register.
- 5. Unlock the write by writing the 0x55555555 pattern to the UNLOCK_WRITE register.
- 6. Start the writing process by writing the OxAAAAAAA pattern into the WRITE_START register.

Flash Memory Map

CTRL_OP.SIZE[1:0	Number of Bytes	ADDR[1:0]	Description
00	1	00	One Byte written at address ADDR
00	1	01	One Byte written at address ADDR
00	1	10	One Byte written at address ADDR
00	1	11	One Byte written at address ADDR
01	2	00	Two Bytes written at address ADDR and (ADDR + 1)
01	2	01	Two Bytes written at address ADDR and (ADDR + 1)
01	2	10	Two Bytes written at address ADDR and (ADDR + 1)
01	2	11	FORBIDDEN
10	3	00	Three Bytes written at address ADDR, (ADDR + 1) and (ADDR + 2)
10	3	01	Three Bytes written at address ADDR, (ADDR + 1) and (ADDR + 2)
10	3	10	FORBIDDEN
10	3	11	FORBIDDEN
11	4	00	Full word written at address ADDR
11	4	01	FORBIDDEN
11	4	10	FORBIDDEN
11	4	11	FORBIDDEN

• Note

The word write process can take up to $40\mu s$.

6.4 Flash Code Portection

The controlled access to the flash content is based on disabling all communications with the debug interface, therefore preventing any external attack. Hence, the application code is still able to modify the Flash content. Upon Power-On Reset or Normal Reset, MCU core disables the communication with the debug interface for a small time interval (8192 system clock cycles). If the application needs to be protected it is mandatory to set the protection register with the appropriate code in the beginning of the initialization process and before the internal hardware enable the debug communication. In other words, if during this time interval the protection register is loaded with a specific pattern, then the communication remains disabled after the end of this interval and stays disabled until this register is loaded with a different pattern. To allow for debug communication the application has only to write a different value in the lock register. If a part is protected, the emulator can still erase and program the part, but first it will be required to erase the Flash content, therefore protecting it.

FLASH_SFRS->CODE_PROT 0xF2E11047;

//Code protection activated

Note

If code protection is necessary it is important to consider the time it takes from the moment the part is reset until the execution reaches the main function. In some exceptional cases where the initialization of the system (stack, heap, global variables) take more than 8K clock cycles it may be necessary to add code directly in the initialization routine.

6.5 Flash Characteristics

The flash endurance sector is greater than 20,000 cycles. The data retention is greater than 100 years at 25C.

7 Flash Oscillator

The Flash Controller needs a clock to measure some timings to controller the flash operation properly. The clock of the processor cannot be used since it may vary for a given product. The dedicated Oscillator is used to provide a 4Mhz clock to the flash controller. This section describes the behavior of the Flash Oscillator and is not relevant to the end user of the product. The Flash controller is in charge of starting and stopping the oscillator during the write/erase operations.

8 Systick Timer

This timer is an optional peripheral created by ARM and implemented in the Cortex M0 160/8. It is fully described in the Cortex-M0 Devices Generic User Guide (Chapter 4.4 Optional System Timer, Systick)

Its interrupt can be enabled as follows:

NVIC_EnableIRQ(SysTick_IRQn);

9 Timers (0, 1 and 2)

The MCU implements three identical timers: Timer0, Timer1 and Timer2. All three timers operate using the system clock as clock source. They increment at the system clock rate starting from the loaded value in the counter until they roll over from 0xFFFFFFFF to 0x00000000. At this point

an interrupt is generated if enabled. The interrupt routine is responsible for reloading the value if needed as this timer does not auto-reload the original content.

9.1 Timer Operation

The operation of the Timers is quite straightforward. Load the TIMERx.COUNT with the required initial value, enable the timer and if required also enable the related interrupt. If the interrupt is enabled an additional code to handle the interrupt must be added.

Code Example1

If we are running from a 15MHz System Clock and we want to use timer1 to generate a time delay of 2msec without interrupt we can calculate the necessary timer counter:

```
T = 2msec \times 15MHz = 30000
```

Given that the timer counts to roll from 0xFFFFFFF to 0x00000000 we have to take the negative value. Code fragment:

```
*TMR1REG = -30000;  //Load counting value

*TMR1CTRL = 1;  //Enable timer

while( TMR1REG < 0 );  //Wait to reach 0

*TMR1CTRL = 0;  //Disable timer
```

Using the interrupt would require to have it enabled and the interrupt handler defined. The following code generates an interrupt every 2msec under the same conditions:

10 Watch Dog Timer

The MCU implements a WDT (Watch Dog Timer) that can operate in one of two ways:

- Interrupt Mode: In the event of a WDT rollover an interrupt will be generated.
- Reset Mode: In the event of a WDT rollover the microcontroller will reset.

The WDT supports Reset, Enable, status/flag and clear functions. It integrates a pre-scaler that can divide the system clock by 213, 219, 222 or 232. It means that the WDT internal counter will count from 0 to the pre-scaler value at the system clock speed and trigger if not cleared. For instance, a system running from a 30MHz system clock and 222 pre-scaler value will trigger the WDT after approximately 0.14 seconds if not cleared properly and in time by the application.

11 Block Transfer Engine

11.1 Introduction

Due to Verne's serial interface, there is a large overhead for individual data transfers between the ASIC die and MCU. For most MCU application transfers this is acceptable, but a block transfer mode has been implemented for those cases where this is not (e.g. Ethernet or USB).

MCU configures:

- base address
- · number of bytes
- whether to increment address (or access same address repeatedly)
- read/write

MCU then writes a start indication to initiate the transfer.

• Special format message for reduced overhead for this transfer

When block transfer happens, stall CPU only if

- It is going to access serial bus or SRAM interface
- The block transfer read data not yet received

11.2 Interrupt

An interrupt is generated at the end of each transferred block. This can be used to allow the software do things like scatter gather by software. Otherwise, the software can poll the start bit.

11.3 Usage Example

12 Electrical Characteristics

over junction temperature range -40°C to 125°C and recommended supply voltage (unless otherwise noted)

Electrical Characteristics

Parameter	Test Conditions	Min	Тур	Max	Unit	
MCU core supply	VDD	1.35	1.5	1.65	٧	
Flash Supply	VFLASH	1.35	1.5	1.65	V	
IO Supply	VIO	3.0	3.3	3.6	V	
System Clock				30	MHz	
Active Current			60	80	uA/MHz	
Power On Reset						
Threshold Voltage	DC level	0.9		1.0	٧	
	dv/dt based			tbd	V/s	
RC Oscillator						
Frequency			1		MHz	
Frequency accuracy	Post trim	-10		10	%	
Flash Memory (Only)						
Sector Endurance	100K Preferred May need additional qualification	20K			Cycles	
Data Retention	@25degC	100			Years	

Parameter	Test Conditions	Min	Тур	Max	Unit
Active Read Current	@30MHz, 125C			3.5	mA
Active Write Current				2.5	mA
Active Erase Current				2.0	mA
Standby Current			80	150	uA
Deep Standby Current			0.05	6	uA
Read access time				25	ns
Sector Erase time		4		5	ms
Chip Erase time		20		40	ms
Byte Program time				7.5	us
Wake up time from Deep standby current				10	us

6 LIN Interfaces

iND83207 contains two integrated LIN PHY on the LIN1 and LIN2 pins, plus a LIN master controller and a LIN slave controller. These circuits enable iND83207 to connect to two different busses for low speed vehicle serial data network communication using the LIN protocol.

The LIN controllers implement the datalink layer of the LIN Protocol Specification. LIN uses a single master / multiple slave concept for the message transfer between nodes of the LIN network. The LIN controller core interfaces to the micro-controller to enable the transmission and reception of message frames. It includes a wake-up function using a dominant (low) bus pin message.

Each LIN transceiver can be configured as master or slave. Each transceiver can be connected to either the master or slave controller. By this mechanism, LIN1 and LIN2 can be configured to operate as master and slave, with the master operation on either LIN1 or LIN2.

6.1 LIN features

- 2 LIN controllers and transceivers (1 slave and 1 master with swappable controllers and configurable transceivers)
- Support for LIN specification 2.2A
- Compliant with SAE J2602 (rev J2602-1_201211).
- Backward compatibility to LIN 1.3
- Programmable data rate between 1 Kbit/s and 20 Kbit/s (for master)
- Automatic bit-rate detection (for slave)
- 8-byte data buffer
- 8-bit host controller interface
- The voltage at the LIN1/LIN2 pins can be read using the housekeeping ADC, which is useful for system diagnostics

6.2 Support for Slave Node Position Detection (SNPD)

In any system which uses identical ultrasound modules built around an iND83207 device, it must be possible to place an identical module at any position within the system and for that module to be able to work out where it sits within that system. The modules in these systems can use 4 pins or more. iND83207 includes circuits which enable this function.

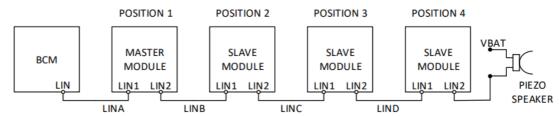
6.2.1 4-pin module topologies

A 4-pin module connects the following pins to iND83207: VBAT, GND, LIN1 and LIN2. These modules can be used in a variety of system topologies. The iND83207 LIN SNPD solution is required to support a number of different system topologies, including

- Standalone systems (no LIN to BCM)
- Single LIN busses connecting up to 12 devices
 - o allowing a single LIN bus for front and rear bumpers, each with up to 6 sensors

The topologies which must be supported are detailed below.

Topology 1

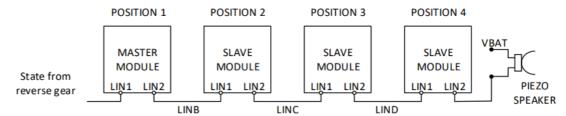


Module topology 1

Module topology 1 has the following features:

- Master module in position 1 communicates with BCM via LIN (on bus LINA)
- All bumper modules communicate over a shared local LIN bus where the master module operates as the LIN master and the slave modules all operate as LIN slaves
 - LINB, LINC, LIND operate as a single LIN bus to be explained later
- The final slave module (position 4 in this example) may be required to drive a speaker from its unused (LIN2) module pin
- The number of modules on this bus can reach 12 maximum
 - 6 modules/bumper with both bumpers communicating on a single local LIN bus

Topology 2

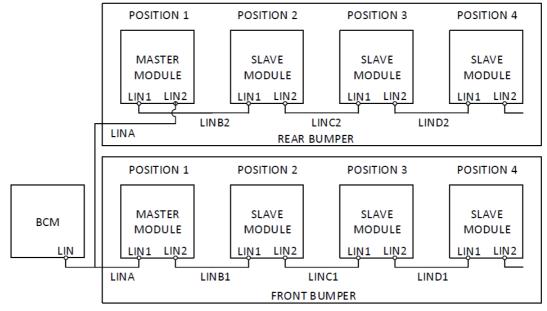


Module topology 2

Module topology 2 has the following features:

- "Standalone system": no BCM to activate the system operation; master module in position 1 is enabled by some car event such as reverse gear engaged
 - Commonly this would be used to drive the LIN1 pin of the master module low against the LIN master or slave pull-up
- Otherwise this topology is the same as topology 1
- No communication back to a BCM is possible
 - The only driver feedback is via the speaker

Topology 3



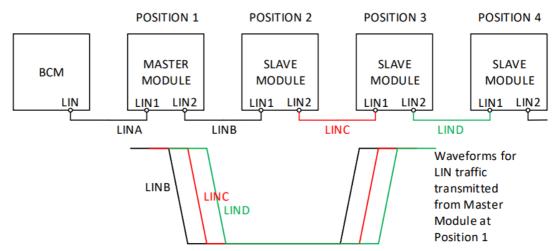
Module topology 3

Module topology 3 has the following features:

- Similar to topology 1 but with both front and rear bumpers on the same LIN bus to the BCM
- Front / rear bumper master modules identify themselves through BCM connection to LIN1 (FRONT) vs LIN2 (REAR)

6.2.2 Indie's SNPD

- Each slave module operates as a LIN "repeater"
- Each module can
 - $\circ \;\;$ Drive the bus when responding to a master request
 - Drive a "dominant" state observed on LIN1 out on LIN2 (to propagate signals "to the right")
 - $\bullet \quad \text{Drive a "dominant" state observed on LIN2 out on LIN1 (to propagate signals "to the left")} \\$
- Figure 7 shows a LIN packet being transmitted from the master module to all the slaves



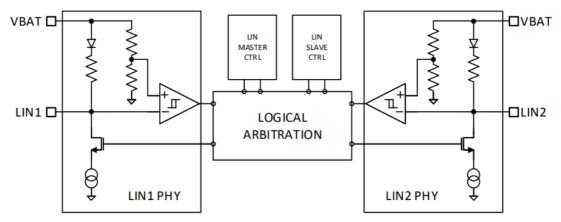
LIN traffic being transmitted from the master module

Indie's SNPD is different from a normal LIN bus in the following ways:

- LINB, LINC, LIND are each independent LIN busses which each have only two nodes
- One of these nodes would be defined with a master pull-up, and one with a slave pull-up
 - LIN1 = slave pull-up; LIN2 = master pull-up
- For the slave modules
 - all LIN1 ports would be connected to the LIN slave controller
 - LIN1 could be driven by the slave controller

- LIN2 would "repeat" a dominant state on LIN1
- · Passing messages from left to right
- LIN1 would "repeat" a dominant state on LIN2
- · Passing messages from right to left

Indie's SNPD implementation is shown in Figure 8 and operates as described below.



indie's SNPD implementation using a repeater architecture

- Each LIN pin (LIN1/LIN2) retains the full LIN electrical interface
- LIN1 / LIN2 PHYs are multiplexed to the LIN master or LIN slave controllers
- A simple logical arbitration block is added, which performs the following tasks
 - Passes through RX and TX data to the relevant controller
 - o passes a dominant state from LIN1 to LIN2, or from LIN2 to LIN1, when it is enabled to do so
 - Measures the repeater delay in each direction

The repeater delay illustrated in Figure 7 needs to be considered to ensure that it does not adversely affect the system operation in any way. There is a delay as the LIN signal is "repeated" along the sequence of independent LIN busses

- LINB -> LINC -> LIND, for a signal sent out from the master module at position 1
- This means that not all slaves receive the message from the master at the same time, which could be an issue for one of two
 - 1. The LIN protocol timings require a slave to respond within a given time
 - 2. All slaves should receive the commands at the same time
 - If not, this could become an error in TOF calculations for the modules which are listening (but not transmitting)

iND83207 will ensure that the TOF error will be insignificant, and LIN specifications will be met. The design calculations and ideas for how to ensure this are given below:

- The delays will be short enough that the TOF error is insignificant
 - The delays are dependent on LIN bus capacitance, which is not known ahead of time, so the delay will not be fixed
 - We shall calculate the maximum possible delay and ensure that the LIN system operates within specification for the longest possible bus (12 modules)
- We shall also measure the propagation delay (in both directions) to enable the system to null out the delays to ensure TOF calculations are accurate to 1cm
 - We will measure the delay between the signal "received" on one LIN port, and the signal "received" at the other LIN port, of the same device
 - Apart from a very small error (due to the propagation of the LIN signal along the wiring harness) this is an accurate
 measure of the delay between the LIN command received at that module and the same LIN command received at the
 next module

Note: if it is discovered during the design phase that the proposed repeater architecture does not

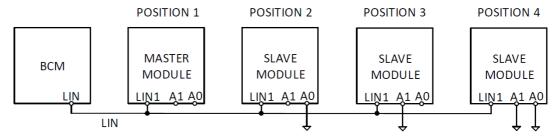
work, there are other options for implementing the required SNPD functionality. The most obvious is to implement a switch that electrically connects LIN1 to LIN2. Control of this switch would be via firmware.

6.2.3 Other module types

There are other module types where SNPD may be done in a different way. These systems have additional module pins which can be used to identify the address of any module via bumper wiring.

3 LV GPIOs are provided which can be used to encode up to 8 locations via 3 binary settings. These 3 LV GPIO pins are wired to the module pins through a protection resistor. Pin pull-ups are enabled which sets the default state of that pin to "1", which is detected when that module pin is left floating. The wiring harness can pull any of the module pins to 0V, which can be detected at the pin using the HKADC to identify a "0".

Such a topology is shown below, with this example using 2 GPIOs to select 4 addresses.



SNPD using LV GPIOs

6.3 LIN1 / LIN2 GPIO mode

Additionally, the LIN1 and LIN2 pins can be operated as GPIOs. The outputs can be pulled up using either the master or slave pull-up. The outputs can be pulled down using the LIN pull-down driver. These operations can be directly controlled from configuration registers, bypassing the LIN controller.

6.4 LIN1 / LIN2 pins as a speaker driver

Some system topologies (especially "standalone") need to drive a speaker. One desire is to do this in a way where every sensor module is identical. This could be done if the speaker connected to the last module on the LIN network, with the speaker connected to the module's unused LIN1 or LIN2 pin.

Speaker types that need to be driven from the iND83207 pins are:

- "Active" speaker modules which incorporate electronics to drive the power required by the speaker
 - $\circ~$ These require only a "logical" input which can be driven directly from the LIN1 / LIN2 pin
- Piezo speaker modules
 - These can be driven with current-limited pull-down drive

6.4.1 Electrical requirements

For driving a "logic" signal to control an active speaker, the same output structures as are available for GPIO mode should be used.

For driving a piezo speaker, the LIN1 / LIN2 pins will have a current-limited pull-down mode.

The selectable pull-down values have been listed in Electrical Specifications.

6.4.2 Drive patterns

For both GPIO and Piezo drive iND83207 will include functionality to enable different bit patterns to be driven on to the LIN1 / LIN2 pins:

- · Bit-banging direct from firmware
- PWM controlled

6.5 High-speed mode for end-of-line (EOL) testing

LIN communication is limited to a maximum of 20kHz under all conditions.

A guaranteed faster baud-rate capability is required for iND83207 to support EOL testing. This will be achievable on iND83207 within certain constraints:

- Limitation of environmental conditions (supply, temperature, wiring parasitic capacitance and resistance, perhaps external pull-up resistors)
- Limitation on protocol capability
 - Full LIN protocol may not be supported; shorter messages using the standard UART will enable faster baud rates

7 GPIOs

7.1 Low-voltage GPIOs, PA[4:0]

iND83207 provides five general-purpose I/O pins on PA[4:0]. These pins are supplied from the VDD3P3 voltage rail and provide the following features

- strong push/pull output drive
- pin pull-up and pull-down resistors which can be independently enabled
- input logic detection with pin state readback to the microcontroller
- · analog input to ADC
- maskable interrupt on pin state change either level-based or edge-triggered

7.2 High-voltage GPIOs, PB[2:0]

iND83207 provides three general-purpose high-voltage I/O pins on PB[2:0]. These pins are supplied from the VBAT voltage rail and provide the following features

- strong push/pull output drive
- pin pull-up and pull-down weak currents
- input logic detection with pin state readback to the microcontroller
- · analog input to ADC
- $\bullet \quad \text{maskable interrupt on pin state change either level-based or edge-triggered} \\$

7.2.1 High voltage GPIOs as module input pins

These pins can be used as module input pins. There is a requirement for a series resistor in the region of $100k\Omega$ to protect this pin from load-dump testing. It is also anticipated that a capacitor of at least 47nF is placed at the module pin.

7.2.2 High voltage GPIOs as module output pins

These pins can be connected up to be used as module input pins. The pins provide a controlled current source which can be used to drive external ground-referenced loads.

Short-circuit protection can be implemented by firmware using the housekeeping ADC to read the voltage at the device pin.

8 Clock sources

iND83207 provides three integrated clock sources.

There is an auxiliary oscillator running at 10 kHz. This oscillator is always running and is used for system power-up and power-down control. The system clock is normally provided from a second oscillator running at 16MHz. In addition, there is a high-accuracy reference clock for timing measurement.

It is possible for firmware to disable the 16MHz oscillator, in which case the system will revert to running from the auxiliary oscillator.

8.1 Correction for clock inaccuracy using LIN SYNC

The iND83207 system clock is trimmed at production test to the 16MHz target frequency, but this frequency may drift over temperature.

iND83207 provides the facility to use the LIN SYNC field as a clock reference. This allows for an accurate measurement of the system clock rate to be made relative to the SYNC reference frequency. Using this measurement, any drift in the system clock rate can be compensated for in the time-of-flight calculations. A single register can be read which gives a value which can be used to scale the oscillator frequency.

8.2 Integrated high-accuracy calibrated reference oscillator

iND83207 integrates a high-accuracy oscillator which is calibrated at final production test. In the case of systems which have no accurate LIN SYNC field to measure as a clock reference, this integrated clock can be used as an alternative.

A frequency counter function is provided, which enables the frequency of the system clock (nominally 16MHz) to be measured with respect to the high-accuracy reference clock. This measurement can be used, as with the LIN SYNC field measurement, to scale any calculations which use the system clock as their reference.

9 Power management unit

iND83207 implements a power management unit which derives all of the supplies required by iND83207 from the VBAT pin, which is directly connected to the vehicle battery.

iND83207 requires a 3.3V supply for core analog and digital functions, plus a 1.5V supply for the core logic of the microcontroller. These supplies require external decoupling capacitors on the VDD3P3 and VDD1P5 pins.

iND83207 is safe to load-dump transient voltage spikes.

9.1 Supply monitoring

iND83207 incorporates a power-on reset circuit which ensures that the system resets into the same state whenever the battery voltage is connected for the first time. In addition, while in the active state, iND83207 monitors both generated supplies with brown-out reset (BOR) circuits. When these circuits indicate a failing supply, the system can either be fully reset immediately, or an interrupt can be generated which the MCU can use to implement a controlled power-down sequence.

9.2 Watchdog timers

iND83207 incorporates two watchdog timers, one on the analog ASIC and one on the micro-controller itself. When either of these timers expire, they can be used to reset the iND83207 device.

10 Housekeeping ADC

An 8-bit SAR ADC provided on iND83207 serves the purpose of monitoring voltages at many of the device pins, plus junction temperature. An on-board adjustable ADC reference is provided, but this is limited to approximately 2.6V maximum. Any pin voltages which may be above this level are divided down to place them within the ADC input range.

Note that the housekeeping ADC must not be used while the ultrasound receiver (USRX) is in operation.

The full list of ADC channels is

- Supplies: VBAT, VDD3P3, VDD1P5
- PA[4:0]
- PB[2:0]
- LIN1 / LIN2
- VPTAT voltage proportional to absolute temperature of the silicon

11 Clock Calibration

11.1 CCAL Overview

The Clock Calibration (CCAL) module provides a frequency counter function which enables the frequency of a system clock to be measured with respect to an accurate reference clock. This measurement can then be used to calibrate the system clock or scale calculations which use the system clock as their reference.

11.2 CCAL Operation

CCAL performs its frequency counter function through a reference counter, running off the reference clock, and a calibration counter, running off the system clock.

Shown in Figure 11.1, the initial value of the reference counter is set through the INIT_REF_VAL field on the CCAL register bank. When run is set high by writing to the RUN field this initial reference counter value is decremented by 1 at each positive edge of the strobe reference clock. The calibration counter is initialised to 0 and then incremented by 1 at each positive edge of the system clock.

Beginning of frequency counter operation

When the reference counter is decremented to zero the calibration counter is stopped on the next positive edge of the reference clock, Figure 11.2.

End of frequency counter operation

This final value of the calibration count should be equal to,

The clk_sys frequency can then be determined from this final calibration counter value to a resolution of,

frac{ref_clk frequency}{clk_sys frequency times (INIT_REF_VAL + 1)}.

Thus, the maximum achievable resolution achieved by the CCAL module is dictated by the width of the ref counter REF_CNT_W. The maximum achievable resolution being,

This assumes that the calibration counter width, CAL_CNT_W, is large enough so that,

$$\frac{\textit{ref_clkfrequency}}{\textit{clk_sysfrequency} \times 2^{\textit{REF_CNT_W}}}$$

if not, the calibration counter will overflow.

Note it is possible, if the number of overflows that will occur is known, to determine the correct counter value through,

$$2^{CAL}CNTW \times no.overflows + CALCNTW VAL$$

Example. For a clk_sys frequency of ~16MHz, ref_clk frequency of 1MHz and reference counter width of 7bits the CCAL can determine the frequency of the clk_sys to a resolution of,

$$\frac{1MHz}{16MHz \times (2^7)} = 0.000488 = 0.0488\%$$

11.3 CCAL Configuration

To configure the CCAL module for the frequency counting operation the debug key is enabled and the INIT_REF_VAL is set to an initial value.

The CCAL interrupt can also be enabled. The interrupt will be generated at the completion of the frequency counter operation, on the first positive edge of the strobe reference clock while the reference counter value is 0, shown in Figure 11.2.

The frequency counting operation is initialised by writing a 1 to the RUN field. Once RUN is high the reference counter value will be decremented on every positive edge of the strb_ref_clk. The calibration counter is incremented on the positive edge of the clk_sys at the same time as the reference counter is being decremented.

On the first positive edge of the strb_ref_clk while the reference counter is equal to zero the RUN field is cleared and the CCAL interrupt is generated. The frequency of the sys_clk can then

be determined from the value of the CALCNTR field.

An example of the initial value being set and the frequency counter operation being run is shown below.

```
SYSCTRLA_SFRS->DEBUG_ACCESS_KEY = 0x1DACCE55;

CCAL_SFRS->IRQ.ENABLE.CCAL = 1;

CCAL_SFRS->CCAL.REFOSCENA = 0x1;
CCAL_SFRS->CCAL.INITREFVAL = 0x3F;
CCAL_SFRS->CCAL.RUN = 0x1;

int retries = 100000;

while(retries--) {
   if(CCAL_SFRS->IRQ.IRQ.CCAL) {
      CCAL_SFRS->IRQ.CLEAR.CCAL = 1;
      return EXIT_SUCCESS;
   }
}
```

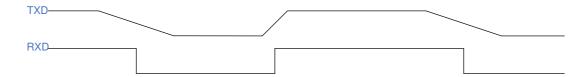
11.4 CCAL Registers

Refer to the ASIC register specification documentation included separately.

12 LIN Transmit Delay Compensation

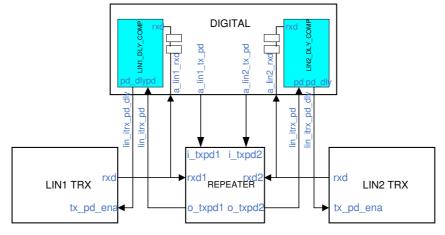
12.1 Overview

The LIN transceiver(itrx_lin) can have unequal delays for rising and falling edges, depending on the load on LIN Bus. As this difference gets significant, it starts to eat up the bit period. In repeater mode these can add up quickly over multiple modules and may end up violating the margin on the minimum bit period. In order to avoid this situation, the rise/fall delays needs to be compensated. For example if the fall delay is more than the rise delay then "0" bit will be shorter and "1" will be longer than the set bit period. In this case we need to delay the application of "1" on the bus to match the difference of fall and rise delays.



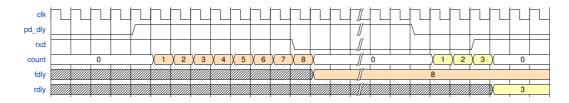
12.2 BLOCK Diagram

The pull down signal at the input of the lin transceiver has been brought in as an input and a delay compensated version of this signal is provided back to the transceiver, for the measurement purpose the retimed rxd signal is used in the lin_dly_comp block. lin_dly_comp is the module responsible for doing the delay compensation. There are 2 instance of this in ioctrla for the 2 LIN transceivers.



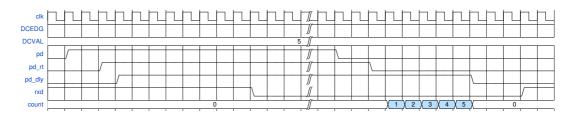
12.3 Measurement

The rise and fall delays are measured in terms of number of system clocks. For Rise Delay(RDLY), the delay counter measure the delay from pd_dly signal being de-asserted to rxd going high. For Fall Delay(FDLY), the delay counter measure the delay from pd_dly signal being asserted to rxd going low.



12.4 Compensation

The compensation is done based on register settings DCEDG and DCVAL. DCEDG sets the edge to be delayed for compensation and DCVAL decides the number of clock cycles it needs to be delayed by. following is an example of compensation of the rise edge, which goes along the example in measurement section.



12.5 Modes of Operations

lin_dly_comp block looks for a falling edge of data(rising edge of pd) first, followed by a rising edge of data(falling edge of pd) to complete a cycle. A cycle may consist of only measurement, only compensation or both depending on the configuration. .. table:: functional configurations

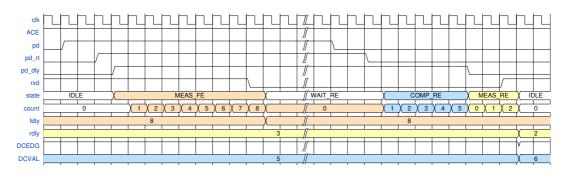
ВҮР	ACE	DME	DCE	Functionality
0	0	0	0	Don't use
1	х	х	х	bypass mode
0	1	х	х	auto compensation mode
0	0	1	0	Measurement only mode
0	0	0	1	Compensation only mode
0	0	1	1	Measurement and Compensation mode

12.5.1 Bypass Mode

In this mode the pd signal is routed straight to pd_dly, without any synchronous delay. Setting this mode, means the legacy design without any involvement of lin delay compensation block.

12.5.2 Auto Compensation Mode

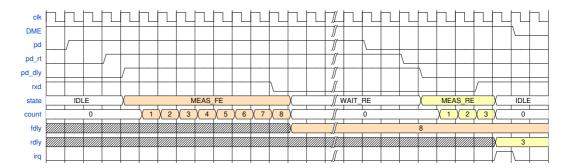
In this mode the lin_dly_comp block measure the rise and fall delays and uses them to compensate the delay in next cycle. Every cycle involves delay compensation of a particular edge depending on the previous measurement and the new delay measurement. The RDLY, FDLY, DCEDG, DCVAL gets updated by the lin_dly_comp block in every cycle.



12.5.3 Measurement Only

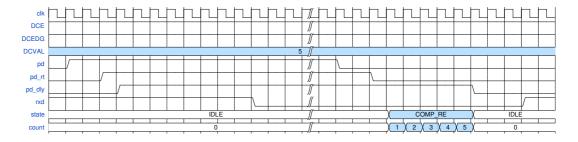
In this mode the lin_dly_comp block measure the rise and fall delays. To execute this mode as shown in table, the DME bit needs to be set, and when the lin_dly_comp block is done with the measurement of rise and fall delays, it will clear the DME, which signifies the measurement is done. At the end of measurement there is also the assertion of lindlycomp interrupt(a single cycle pulse) gets asserted. In the current implementation the interrupts for lin1_dly_comp and lin2_dly_comp are ORed and they are sharing the same vector position with timer3.

lin_dly_comp looks for the falling edge first, to do the FDLY measurement and then the rising edge to do the RDLY measurement to finish the measurement cycle. The firmware can read the FDLY and RDLY and evaluate the DCEDG and DCVAL for compensation.



12.5.4 Compensation Only

In this mode the lin_dly_comp block compensate the rise or fall edge, with the edge selection set by DCEDG and the delay value set by DCVAL. The firmware on the basis of the measurement values can set DCEDG and DCVAL, and setting the DCE enables the compensation feature. If the DCE is deasserted in the middle of a compensation cycle then the lin_dly_comp block finish the current compensation cycle and then goes IDLE.



12.5.5 Measurement and Compensation

In this mode the firmware sets both DME and DCE, It also sets the DCEDG and DCVAL to be used for compensation. The first cycle the lin_dly_comp block does the measurement and the compensation, and clears the DME bit at the end of the cycle, and the next cycle onwards it only does compensation.

12.6 Design Doccumentation

13 USTRX DSP

block diagram...

13.1 Filter Options

Following describes 7 filter options that's available. The gains are not completely normalised, so there needs to be a corresponding correction factor in the firmware.

13.1.1 Bandwidth

The -3dB filter bandwidth δf of the filters are normalised to the transmitted frequency(f_{tx}) in the table An example for calculating the bandwidth for a transmitted frequency f_{tx} = 50kHz, and if filter 4 is selected then

$$\frac{\delta f}{f_{tx}} \times f_{tx} = 0.05469 \times 50 kHz = 2.73 kHz.$$

13.1.2 Group Delay

The group delay in the table is in terms of number of samples at f_{tx} An example for calculating the group delay of the filter in sec for a transmitted frequency f_{tx} = 50kHz, and if filter 4 is selected then

$$gd(ms) = groupdelay(samples) \times \frac{1000}{f_{tx}} = 8.042 \times \frac{1}{50} = 0.16084ms.$$

	Coeffs					
Filter	a1	a2	b	Gain	δf / f _{tx}	group delay
1	986	949	1	0.8264	0.02051	18.875
2	996	969	1	0.8264	0.03174	13.875
3	982	942	2	0.8264	0.04150	10.375

	Coeffs					
Filter	a1	a2	b	Gain	δf / f	group delay
4	975	929	4	1.1019	0.05469	8.042
5	946	877	11	1.0101	0.10840	4.208
6	870	750	41	0.9966	0.21680	2.140
7	779	624	109	1.0009	0.38477	1.236

14 Ultrasound Receive FIFOs

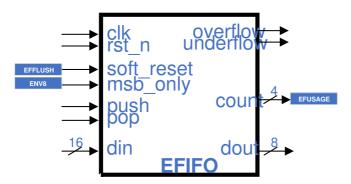
14.1 Overview

There are 2 Data FIFOs dedicated for ultra sound receiver, one for envelope data, and the other one is for frequency data of the received signal. The ustrx core pushes the envelope data(16bit samples) into the envelope FIFO(ENVFIFO), and the firmware can pop data from the ENVFIFO via ESAMPLES register either via WORD accesses or HALFWORD accesses. Similarly the ustrx core pushes frequency counter data(10bit samples) into the envelope FIFO(ENVFIFO), and the firmware can pop data from the FCFIFO via FCSAMPLES register either via WORD accesses or HALFWORD accesses. The 6 MSbits in every half word can be ignored.

NB: one thing to remeber is that the DATA received by the firmware will be in a big-endian format. So incase of a WORD access firmware need to perform a REV instruction, and incase of a HALFWORD access it has to perform a REV16 instruction.

14.2 Details

14.2.1 ENVFIFO



Size & Mode

The size of the FIFO is 8 bytes which means it can hold upto 4 samples of 16bit envelope data, or 8 samples of 8bit data when ENV8 is set. In 8bit mode where only the most significant byte of the envelope sample gets pushed to the FIFO, This mode is selected when the CSR.ENV8 register is set.

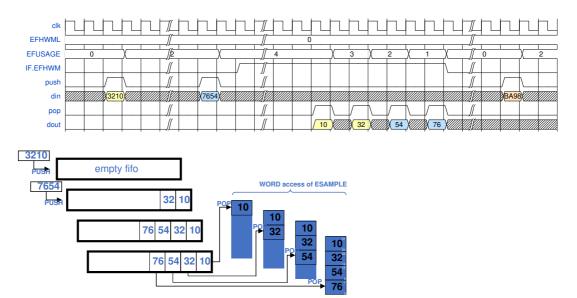
Watermark

CSR.EFIFO.EFHWML can be used to set a High Watermark Level for the ENVFIFO. CSR.IF.EFHWM is the flag to indicate the envelope FIFO is at or above the High Watermark Level CSR.IE.EFHWM can be used to enable the High Watermark Level interrupt for ENVFIFO.

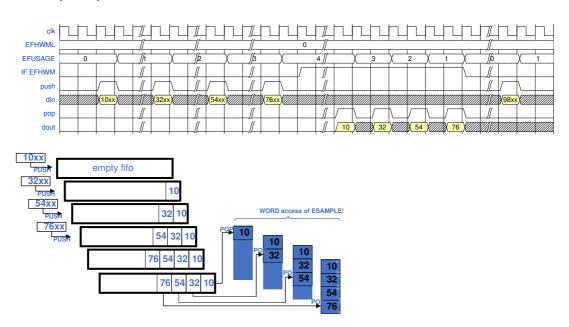
This interrupt is a non sticky interrupt, and doesn't require clear to save firmware load. As the clough interface passes an ievent for rising edge of the interrupt, so the idea is to create an interrupt which has a guaranteed edge on the interrupt everytime the fifo usage crosses the water mark. So that after reading the samples from the fifo while still executing the interrupt handler if (CSR.EFIFO.EFUSAGE >>2) > CSR.EFHWML, then mcu gets another interrupt.

Everytime the fifo usage become equal or above the set water mark, the interrupt goes high and cleared at the last byte read. If the fifo usage is still high then the flag gets set again. it also gets cleared with CSR.EFIFO.EFFLUSH.

16bit mode(ENV8=0)



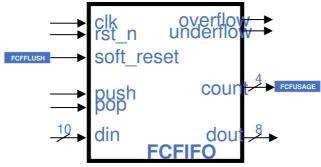
8bit mode(ENV8=1)



Flow Error

There are interrupts for overflow and underflow conditions of the FIFO. CSR.IF.EFOVF flag gets set in case of an overflow condition. CSR.IF.EFUNF flag gets set in case of an underflow condition.

14.2.2 FCFIFO



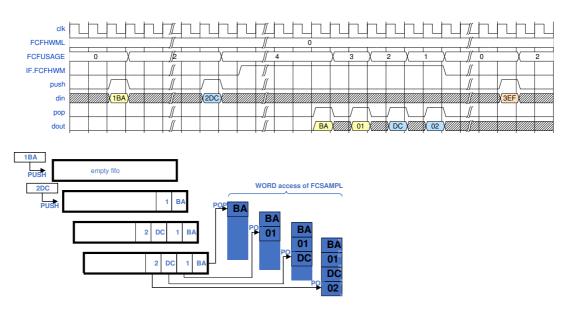
Size & Mode

The size of the FIFO is 4x10 bits which means it can hold upto 4 samples of 10bit envelope data.

Watermark

CSR.FCFIFO.FCFHWML can be used to set a High Watermark Level for the FCFIFO. CSR.IF.FCFHWM is the flag to indicate the frequency counter FIFO is at or above the High Watermark Level CSR.IE.FCFHWM can be used to enable the High Watermark Level interrupt for FCFIFO.

This interrupt is a non sticky interrupt, and doesn't require clear to save firmware load. As the clough interface passes an ievent for rising edge of the interrupt, so the idea is to create an interrupt which has a guaranteed edge on the interrupt everytime the fifo usage crosses the water mark. So that after reading the samples from the fifo while still executing the interrupt handler if (CSR.FCFIFO.FCFUSAGE >>2) > CSR.EFHWML, then mcu gets another interrupt. Everytime the fifo usage become equal or above the set water mark, the interrupt goes high and cleared at the last byte read. If the fifo usage is still high then the flag gets set again. it also gets cleared with CSR.FCFIFO.FCFFLUSH.



Flow Error

There are interrupts for overflow and underflow conditions of the FIFO. CSR.IF.FCFOVF flag gets set in case of an overflow condition. CSR.IF.FCFUNF flag gets set in case of an underflow condition.

15 Digital Features

15.1 Watchdog timers

iND83207 incorporates two watchdog timers, one on the analog ASIC and one on the microcontroller itself. When either of these timers expire, they can be used to reset the iND83207 device.

15.2 UART

In addition to the LIN master and slave controllers, HAN will incorporate an additional UART controller.

The UART can be multiplexed to the PA[1:0] pins to operate in full duplex mode, or can be connected to the LIN1 or LIN2 pins to operate in half-duplex mode.

15.3 PWM generators

Han will incorporate a single PWM generator. Firmware programs the frequency and duty cycle, and selects which pins each of the PWM blocks is to control. The PWM blocks can control the following pins:

- LIN1
- LIN2
- PA[4:0]
- PB[2:0]

16 Device traceability

iND83207 is implemented using two silicon die which are bonded together in the package. One die ("the micro-controller die") implements the microcontroller subsystem (M0 + peripherals, Flash, RAM). The other die ("the iND83207 analog ASIC die") implements all the other iND83207 functions.

When supplied to the customer, both die will be programmed with unique IDs which will allow full tracing of the manufacturing flow for those individual die.

The micro-controller die will allocate Flash memory locations to store this information. The iND83207 analog ASIC die will incorporate a one-time-programmable (OTP) memory array for this purpose. Programming of this OTP will only be possible at the time of production testing.

17 Register map

17.1 USTRX

Ultrasound TRX Registers

USTRX CSR control and status register for interrupt and FIFOs IE: interrupt enable, IF: interrupt flag, EFIFO: envelope FIFO, FCFIFO: frequency counter FIFO 31 30 29 28 27 22 21 20 19 18 17 16 15 14 13 12 11 10 9 8 В С D E F G 0 Р R S Т U v w Α L Ν Q Bit(s) Field Description 31:28 **FCFUSAGE** current usage of the frequency counter FIFO number of BYTE(s) in the frequency counter FIFO В 27 **FCFFLUSH** flush the frequency counter FIFO WO n/a С 24 **FCFHWML** frequency counter FIFO high watermark level r/w 0 Number of WORDS in FCFIFO which generates FCFHWM interrupt. Interrupt flag asserts when (FCFUSAGE/4) > FCFHWML. ex: FCFHWML=0, can generate FCFHWM interrupt when FCFUSAGE gets to 4 D 23:20 EFUSAGE current usage of the envelope FIFO n/a ro number of BYTE(s) in the envelope FIFO Ε 19 **EFFLUSH** flush the envelope FIFO n/a F 18 ENV8 read envelope as 8-bit MSB only 0 When set, only MSByte of envelope sample is pushed into FIFO, otherwise the whole 16 bit sample gets pushed into the FIFO G 16 **EFHWML** envelope FIFO high watermark level r/w 0 Number of words in ENVFIFO which genererates EFHWM interrupt. Interrupt flag asserts when (EFUSAGE/4) > EFHWML. ex: EFHWML=0, can generate EFHWM interrupt when EFUSAGE gets to 4 Н 15 **TXSEQ** transmission sequence end interrupt flag dual 0 can be read for status, write a '1 to clear the flag **TXBRST** transmission burst end interrupt flag dual 0 can be read for status, write a '1 to clear the flag J 13 **FCFUNF** frequency counter FIFO underflow interrupt flag dual 0 can be read for status, write a '1 to clear the flag EFUNF (-) К 12 envelone FIFO underflow interrunt flag faub can be read for status, write a '1 to clear the flag FCF0VF frequency counter FIFO overflow interrupt flag 0 L 11 dual can be read for status, write a '1 to clear the flag 10 **EFOVF** envelope FIFO overflow interrupt flag dual 0 can be read for status, write a '1 to clear the flag Ν 9 FCFHWM frequency counter FIFO high water mark interrupt flag 0 ro reads 1 if frequency counter FIFO is at or above set water mark 0 8 **EFHWM** envelope FIFO high water mark interrupt flag ro reads 1 if envelope FIFO is at or above set water mark Ρ 7 **TXSEQ** 0 transmission seauence end interrupt enable r/w TXBRST Q 6 transmission burst end interrupt enable r/w R 5 **FCFUNF** frequency counter FIFO underflow interrupt enable 0 FFUNE S 4 envelope FIFO underflow interrupt enable r/w FCF0VF frequency counter FIFO overflow interrupt enable 0 Т 3 r/w U 2 **EFOVF** envelope FIFO overflow interrupt enable r/w 0

٧

W

1

0

FCFHWM

EFHWM

frequency counter FIFO high water mark interrupt enable

envelope FIFO high water mark interrupt enable

0

r/w

				US	TR)	X		TXC	TRI	L																		0×5	5000	000	4
							t	trans	mit c	ontro	ols																				
31	30	29	28	27	26	25	24	23	22	21	20	19	18	17	16	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Α		В		С	D	E	F			G				Н				ı			J			K				L	-		

#	Bit(s)	Field	Description	Туре	Reset
Α	31	LRSWAP	swap the left and right drive signals	r/w	0
В	30:28	TX2PD	TX2 pulldown select This setting is irrelevant during transmission. TX2PD<2> enables a 25 Ω pull-down. TX2PD<1> enables a 50 Ω pull-down. TX2PD<0> enables a 100 Ω pull-down	r/w	0
С	27	FCENA	frequency counter enable Enable for receive period detector	r/w	0
D	26	RXENA	Envelope receiver enable Enable for evelope receiver enable	r/w	0
E	25	TXDMY	Dummy transmit burst flag If set, transmit burst does not activate drivers	r/w	0
F	24	TXENA	Transmit enable Drive burst transmit enable	r/w	0
G	23:19	CLK2	Increment to frequency division Increment to frequency division from system clock to ultrasound frequency	r/w	0
Н	18:16	CLK1	Base frequency division Base frequency division from system clock to ultrasound frequency	r/w	0
I	14:12	SQ3	Number of resistive drive cycles Number of resistive drive cycles after last drivelet	r/w	0
J	11:9	SQ2	Number of table antiphase drive cycles Number of squelch drivelets to use after antiphase drive	r/w	0
K	8:6	SQ1	Number of antiphase drive cycles Number of antiphase drive cycles to execute after burst	r/w	0
L	5:0	TXCYCLES	Number of drive cycles Number of drive cycles, 0 - continuous drive. Maximum allowed value is 'd32	r/w	0

	l	JSTRX	ENVFIFO	0x5000	80000
			Envelope detector FIFO		
31 30	29 28	27 26 2	5 24 23 22 21 20 19 18 17 16 15 14 13 12 11 10 9 8 7 6 5 4	3 2	1 0
			А		
#	Bit(s)	Field	Description	Туре	Reset
A	31:0	ESAMPLE	S Envelope FIFO read Register envelope FIFO can be read via this register. Received data will be ordered as big-endian. Word(32bit) access is highly recommended for speed. Halfword(16bit) access is also allowed. single Byte access can be misleading due to endianness and not recommended. REV/REV16 instructions can be used on received data to alter the endianness. independent of access type, always keep the base address for reading from the register same ie the Byte address of the lowest byte.	ro	n/a

USTRX	FCFIF0	0×5000000C
	frequency counter FIFO	
31 30 29 28 27 26 2	5 24 23 22 21 20 19 18 17 16 15 14 13 12 11 10 9 8 7 6 5 4	3 2 1 0
	A	

#	Bit(s)	Field	Description	Туре	Reset
Α	31:0	FCSAMPLES	frequency counter FIFO read Register frequency counter FIFO can be read via this register. Received data will be ordered as big-endian. Word(32bit) access is highly recommended for speed. Halfword(16bit) access is also allowed. single Byte access can be misleading due to endianness and not recommended. REV/REV16 instructions can be used on received data to alter the endianness. independent of access type, always keep the base address for reading from the register same i.e the Byte address of the lowest byte	ro	n/a

					l	JST	RX		CF	G																			0×5	5000	001	0
									Vai	rious	con	figs																				
3:	1	30	29	28	27	26	25	24	23	22	21	20	19	18	17	16	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
		Α			В			С					Г)	E	Ē	F					(3			Н				ı		

#	Bit(s)	Field	Description	Туре	Reset
Α	31:29	ENVDV	Post-rectifier decimation value Post-rectifier decimation value. Decimation factor is (ENVDV+1). This decimation have a gain factor (ENVDV+1)/2^(ceil(log2(ENVDV+1)))	r/w	0
В	28:27	IQDV	Pre-rectifier decimation value Pre-rectifier decimation value. Decimation factor is 2^(IQDV+1)	r/w	0
С	25:24	FCDBNC	Frequency counter edge debounce Period detector debouncing control 0x0 — feature disabled 0x1 — 4 cycles of system clock 0x2 — 16 cycles of system clock 0x3 — 64 cycles of system clock	r/w	Θ
D	19:18	AUTOFC	Automaic frequency counter enable Configuration for automatically enabling the period detector from transmit sequence	r/w	0
Е	17:16	AUT0RX	Automaic receiver enable Configuration for automatically enabling the envelope receiver from transmit sequence	r/w	0
F	15	RXBIAS	Receiver bias enable Receiver bias enable	r/w	0
G	11:8	SQ3STR	Resistive drive strength Drive strength during post-burst resistive damping	r/w	0
Н	7:5	DTIME	Driver dead time control Driver dead time control	r/w	0
I	4:0	STR	Transmit drive strength	r/w	0

	l	JSTRX	RX	DSP																			0×5	5000	001	4
			Enve	elope rece	eiver L	DSP	config																			
31 30	29 28	3 27 26 2	25 24	23 22	21	20	19 1	8 17	7 16	15	14	13	12	11	1	0	9	8	7	6	5	4	3	2	1	0
			Α						В										(2						D
#	Bit(s) Field		Descrip	tion																		Ту	ре	Re	set
Α	28:2	2 B		IIR feedf IIR feed																			r,	/w	()
В	21:1	2 A2		Second I Second																			r/	/w	()
С	11:	2 A1	First IIR feedback coefficient First IIR feedback coefficient													r/	/w	()							
D	(0 UPREQ		IIR coefficient update request Set this bit to request for an update of IIR coefficients. This gets cleared by the core once the coeffs gets absorbed by the DSP. Don't change the IIR coeffs while it's set															r/	/w	()				

USTRX	RXAFE																0×5	5000	001	8
	Receiver ana	log co	onfiguratio	on																
31 30 29 28 27 26	25 24 23 22	21	20 19	18	17 16	15	14 13	12	2 11	10	9	8	7	6	5	4	3	2	1	0
А	В	С	D		Е		F		G		ŀ	4		ı		J	J		K	

#	Bit(s)	Field	Description	Туре	Reset
Α	29:27	RGGN	N side input resistor trim Sets grounded resistor value for N input	r/w	0
В	26:24	RGGP	P side input resistor trim Sets grounded resistor value for P input	r/w	0
С	21	STGBYP	Stage bypass Stage bypass for gain reduction	r/w	0
D	20:18	PG4AV	PG4 gain trim PG4 gain trim	r/w	0
E	17:15	PG3AV	PG3 gain trim PG3 gain trim	r/w	0
F	14:13	PG2RL	PG2 RL trim PG2 RL trim	r/w	0
G	12:10	PG2GM	PG2 GM trim PG2 GM trim	r/w	0
Н	9:8	PG1RL	PG1 RL trim PG1 RL trim	r/w	0
I	7:5	PG1GM	PG1 GM trim PG1 GM trim	r/w	0
J	4:3	LNARL	LNA RL trim LNA RL trim	r/w	0
K	2:0	LNAGM	LNA GM trim LNA GM trim	r/w	0

	U	STRX	DRVNWVR	0×5000	0001C
			Reverse drive amplitude table		
31 30	29 28	27 26 2	25 24 23 22 21 20 19 18 17 16 15 14 13 12 11 10 9 8 7 6 5 4 A	3 2	1 0
#	Bit(s)	Field	Description	Туре	Reset
A	27:0	DRVNWV	Reverse drive amplitude table Reverse drive amplitude table	r/w	0

Enable for output current limit Enable for output current limit

Trim for input to charge pump

Trim for input to charge pump

Transmit supply voltage trim

Transmit supply voltage trim

discharge enable

Transmit charge pump function enable Transmit charge pump function enable

	US	TRX	СР	REG	iS																		0×5	5000	0020	9
			Tra	nsmit	charg	e pur	пр со	ntrols																		
31 30	29 28	27 26	25 24	23	22 2	21 2	20 19	9 18	17	16	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
				Α					E	3	С						D		E	F	G			Н		
#	Bit(s)	Field		De	scripti	on																	Ту	/pe	Res	et
Α	23	DISVE	REG	set	able vr ting th n vreg	is to	ʻ1 wi	II stop		_	-			to '0	. if tl	nis is	not	set a	ınd E	NA i	s '1		r	/W	0	
В	17:16	CLKMO)DE		orge pu s the o	harg	ge pur	np clo	ockinį				A is	'0 th	e ch	arge	pum	p clc	ock w	vill be	idle	at	r	/w	Θ	
					0x 1 -	- cha	rge p	ump	gets t	the S	YSC	LK/	2 syn	chro	nise	d to	risin	g edg	ge of	SYS	CLK					
					0x 2 -	- cha	rge p	ump	gets t	the S	YSC	LK/	2 syn	chro	nise	d to	fallin	ıg ed	lge o	f SYS	CLK					
					0x 3 -	no -	clock	s to tl	he ch	arge	pun	пр														

Indicates charge pump is currently switching
If high then charge pump is currently pumping charge into the reservoir cap

17.2 HKADC

С

D

Ε

F

G

Н

ILIM

VINREG

7 ACTV

ENA

DISCHARGE

VB00ST

15

10:8

6

5

4:0

ADC Control

4

n/a

0

6

ro

r/w

iND83207 B0 v1.1

	Hk	KADC	COI	NF																			0×!	5000	00030
			Con	figuratio	on s	etting	s for	the A	ADC	2															
1 30	29 28	27 26 2	25 24	23 22	2 2	1 20	19	9 18	3 1	7 16	15	14	13	12	11	10	9	В	7	6	5	4	3	2	1 (
	Α	В							С						D		E				F	G	Н	I	J
#	Bit(s)	Field		Descr	ipti	on																	Ту	/ре	Rese
Α	31:28	VREFH		High re Contro where	ols	the hi	gh A	\DC r	refe			-			-	-			F * (VRI	EFH	/ 15)		/W	0×F
В	27:24	VREFL		Low re Contro where	ols	the lo	w A	DC re	efer			-			-				= * (\	/RE	FL/	15)	r	/W	0
С	19:16	VREFGA	AIN	VREF g Contro	ols :	the Al						•		_				_				er is	r,	/W	0xI
D	12:10	SAMPCY	′C	Sample The nu sampli SAMP signal source SAMP 200kC	umb ing P_C' will es w	oer of capac /C=0 have /hich a	itor give set are l	is eq es a sa tled t being	jual amp to si g sai	to (1+ oling cy gnifica mpled	SAM ycle v antly thro	IP_C whice bet ugh	YC) th is ter t a Gl	For long nan t PIO p	all or enou he A oin, it	n-chi _l igh to DC r may	sourd ensu esoluti be ne	ces, re t on.	sett hat t For sary	the off to	inpu -chip set		r,	/W	0
Е	9:8	CLKSEL	-	0x 0x	s th (0 – (1 – (2 –	e cloc SYSC SYSC	CLK,	/8. Fo /16. F /32. F	or a For For	for the n 16M an 16M an 16M an 16M an 16M an 16M an 16M	1Hz S MHz MHz	SYS0 : SYS : SYS	CLK, SCLF SCLF	(, this	s is 1 s is 0	MHz .5MH	lz						r,	/w	0
F	5	CALBUF	=		(0 –	· Norr · Char	nal o	opera resist	atio	n tap coi	nnec	tion					/ADC			ined	ct		r,	/w	0
G	4	GNDOFF	BUF		(0 –	Band	dgap	and	AD	C has	com		_		groun	d is (compe	nsa	ted l	by s	switc	hed	r	/W	0
Н	3	BUFENA	4	Buffer Set to make specifi is used specifi should	ena a se icat d by icat d be	able theries of ion. Exist ion. A	of co ach uto- ser ider	ADC zero ies of	sior con fun f at alid.	ns on t nversion. least 1 If the	he A on is: Aftei 10 cc ADC	DC sues r eac onve C ref	beformation before the control of th	re the ock thes oc sh ce b	e AD to the se the ould uffer	C re AD refe be ru is di	ferenc C reference In befor Sabled	e co cor ore or	omes nes the o	s wi uffe clos out	ithin er wh ser to put o	iich o data	r,	/w	0

Full range
Set this bit for ADC reference voltages based on the full range of the supply voltage

Set this bit for ADC reference voltages based on the full range of the supply voltage

Selects the ADC operating mode. Please use the default setting

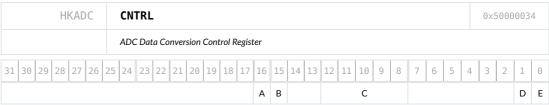
FULLRG

MODE

1:0

r/w

0



#	Bit(s)	Field	Description	Туре	Reset
Α	16	GUARD	GUARD for ADC input Mux Switching if asserted disables all the ADC input muxing, This needs to be set before changing the INSEL. This sequence is enforced to avoid the shorting of channels during the INSEL change	r/w	1
В	15	OUTENABLE	PAO select enabled for bringing out ADC Input Enables the GPA[0] select to bring out the ADC input selected by INSEL. Debug purpose only — only accessible when 'debug access' is enabled	r/w	Θ
C	12:8	INSEL	ADC Input Select Selects the input signal to be measured by the ADC 0x0 - PA[0] 0x1 - PA[1] 0x2 - PA[2] 0x3 - PA[3] 0x4 - PA[4] 0x5 - VBOOST, ignore for zubat 0x6 - PB[0] 0x7 - PB[1] 0x8 - PB[2] 0x9 - VDD1P5 0xa - VBAT 0xb - VPTAT 0xc - LIN1 0xd - LIN2 0xe - TX1, ignore for zubat 0x10 - VDD3P3 - only accessible when 'guard access' is enabled	r/w	0x1F
D	1	CONT	Continuous Conversion Enable if set enables the continuous conversion mode, else it's a single conversion. this is only checked at the end of current conversion	r/w	0
E	Θ	CONVERT	ADC START/STATUS Register Set to start a conversion, gets cleared at the end of single conversion. If CONT is set then this doesn't get cleared at the end of conversion. This can be read to check the current status of ADC conversion	r/w	0

		HKADC	DATA	0x5000)0038
31 30	29 28	27 26 25	24 23 22 21 20 19 18 17 16 15 14 13 12 11 10 9 8 7 6 5 4	3 2 A	1 0
#	Bit(s)	Field	Description	Туре	Reset
Α	7:0	DATA	The result of the last ADC conversion	ro	0

			C_CTRL interrupts ntains the enable, clear, status and active flags for the ADC_CTRL interrupt sources.		
31 30	29 28	27 26 25 2	4 23 22 21 20 19 18 17 16 15 14 13 12 11 10 9 8 7 6 5 4	3 2	1 0
		,	А В С		D
#	Bit(s)	Field	Description	Туре	Reset
Α	24	DATA_RDY	data ready inpterrupt active	ro	0
В	16	DATA_RDY	data ready interrupt status	ro	0
С	8	DATA_RDY	data ready interrupt clear — cleared automatically after each write	WO	0
D	0	DATA_RDY	data ready interrupt enable	r/w	0

0×5000003C

17.3 TDAC

test dac control memory

HKADC

ADCIRQ

		Т	ΓDAC	DA	CCTRL																	0×5	5000	0046	0
				DAC	C Control																				
31	30	29 28	27 26	25 24	23 22	21	20 19	18 1	17 16	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Α	В					С													С)					
#		Bit(s)	Field		Descri	otion																Ту	pe	Res	set
A		31	ENABL	.E	test DA	C end	able															r/	'W	0)
Е	3	30	AUT0P	PUSH	auto pu	ısh en	nable															r/	'W	0)
C	:	27:16	NEXTD	CODE	Next D	AC C	ode															r/	'W	0)
)	11:0	DCODE		Current	DAC	Code															du	al	0)

17.4 LINMB

LINM_ATHENS

	LI	NMB DA	TABYTE03	0×5000	0050
		Da	ta Bytes 0 to 3		
31 30	29 28	27 26 25 24	23 22 21 20 19 18 17 16 15 14 13 12 11 10 9 8 7 6 5 4	3 2	1 0
	А		В С)	
#	Bit(s)	Field	Description	Туре	Reset
Α	31:24	DATABYTE3	Data Byte 3 4th byte of the 8-byte Data Byte	r/w	0
В	23:16	DATABYTE2	Data Byte 2 3rd byte of the 8-byte Data Byte	r/w	0
С	15:8	DATABYTE1	Data Byte 1 2nd byte of the 8-byte Data Byte	r/w	0
D	7:0	DATABYTE0	Data Byte 0 1st byte of the 8-byte Data Byte	r/w	Θ

						Dalasi	ieet -
	LI	NMB DA	TABYTE47			0×5000	90054
		Dat	ta Bytes 4 to 7				
31 30	29 28	27 26 25 24	23 22 21 20 19 18 17 16	15 14 13 12 11 10 9	8 7 6 5	4 3 2	1 0
	А		В	С		D	
#	Bit(s)	Field	Description			Туре	Reset
Α	31:24	DATABYTE7	Data Byte 7 8th byte of the 8-byte Data Byte			r/w	0
В	23:16	DATABYTE6	Data Byte 6 7th byte of the 8-byte Data Byte			r/w	0
С	15:8	DATABYTE5	Data Byte 5 6th byte of the 8-byte Data Byte			r/w	0
D	7:0	DATABYTE4	Data Byte 4 5th byte of the 8-byte Data Byte			r/w	0

	L	INMB C	SR																		0×!	5000	005	58
		Co	ontrol Statu	us Reg	ister																			
31	30 29 28	27 26 25 24	23 22	21 2	20 19	18	17	16	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Α		В				С	D	Ε	F				G	Н	ı	J		К	L		М	N	0	Р
#	Bit(s)	Field	Descrip	tion																	Ту	/pe	Re	eset
A	31	ENHCHK		t cont g this — for	roller	er che	cksu	m		cksur	n typ	pe us	sed i	n the	curi	rent	fram	e by			r,	/w		0
В	27:24	LENGTH	Data Ler The hos by adjus data fiel	t cont	his reg	ister	. If th	nis is	load	led w	ith t	the v	alue							ne	r,	/W		0
С	18	TIMEOUT	Timeout There ar error if i respond TFRAMI if it is re transmit CTRL.D, byte aft wakeup slave do timeout missing	re sevent is explosed to la second to la sec	pectinate and X a ting a dilength ACK or idential and it performs	g da I the neou lata a n and r CTI fier. t dete orm a after	ta from fram t erro ackno l load RL.ST The s ects in ex	om the is or wind owner of the owner o	ne bi not f ill be data regis det nc f hect time	us but finish dete to th), and ster u ects field (c of t s, if t	t no ed v ected e ho I the intil a tim fron he si	slav vithing d too st co he he neou n the rame lave	re do n the o. The ontro t cor end c t err e mas e leng is in	es re max e slav ller (f ntrolle of the or if i eter) v	spor simu ve de for s er de e rec it ha with FRA	nd. If m fra etect elect oes r eptic s tra in 15 ME_	the ame ting into the second of the second o	slave lengt meo receivet the tted s. No (but	h ut er ve or first a te: T	ror The	r	0		Θ
D	17	СНК	Checksu Checksu																		r	0		0
Ε	16	BITMON	Bit Error During 1 the bit t Error if t	Transı ransır	itted.	Durii	ng Re	eceiv	e: th	nis ge	ts se	et wl	nen d								r	0		0
F	15	ACTIVE		indica ter the the ei I by th — no	tes wh e detec nd of t	tion he tr conf s act	of a ansn trolle ivity	corr nissio er	ect S	YNC if th	BR e pr	EAK oces	/ SY	'NC F	FIELI	D se	quen	ce ai	nd it		r	0		0
G	11	INTR	Interupt The LIN the same	core e valu	sets th e as th	ne int	erru	pt ou	ıtpu	t INT	R. T	he b	it ha								r	0		0
Н	10	ERR0R	Lin Error The LIN bit has t	core																е	r	0		0

#	Bit(s)	Field	Description	Туре	Reset
I	9	WAKEUP	The bit is set when the LIN core is transmitting a Wakeup signal or when the LIN core has received a Wakeup signal	ro	0
J	8	COMPLETE	The LIN core will set the bit after a transmission has been successfully finished and it will reset it at the start of a transmission	ro	0
К	6	SLEEP	Sleep Request The bit is used by the LIN core to determine whether the LIN bus is in Sleep Mode or not. The host controller has to set the bit after sending or receiving a Sleep Mode frame or if a bus idle timeout interrupt is requested. The bit will be reset by the LIN core when a wakeup signal is detected	r/w	Θ
L	5	TRANSMIT	Transmit Operation The bit determines whether the current frame is a transmit frame or a receive frame for the LIN node. It has to be set by the host controller $0x0$ — receive operation $0x1$ — transmit operation	r/w	Θ
М	3	RSTINT	Reset interrupt The host controller has to set this bit to reset the STATUS.INTR register and the interrupt request output of the LIN core. A read access to this bit delivers always the value 0	WO	0
N	2	RSTERR	Reset Error The host controller has to set this bit to reset the error bits in status register and error register. A read access to this bit delivers always the value 0	WO	0
0	1	WAKEUPREQ	WakeUp Request The bit has to be set by the host controller to terminate the Sleep Mode of the LIN bus by sending a Wakeup signal. The bit will be reset by the LIN core	r/w	Θ
Р	0	STARTREQ	START Request The bit has to be set by the host controller of a LIN master to start the LIN transmission after loading Identifier, data length and data buffer. The LIN core will reset the bit after the transmission is finished or an error is occurred	r/w	Θ

	L	INMB	co	ONFIG																0×5	000	0005	С
			Со	nfigurati	on Reg	gister																	
31 30	29 28	27 26 2	25 24	23 22	21	20 19	18	17 16	15	14	13 12	11	10	9	8	7	6	5	4	3	2	1	0
							Α		В			С							D				
#	Bit(s)	Field		Descrip	tion															Тур	е	Res	et
Α	21:16	ID		FRAME	ID															r/v	N	0	
В	15:14	PRESCI	L	Prescale Prescal		tting														r/v	N	3	
С	13:9	BTMUL ⁻	Г	Bt Mult Bit time		tiplier														r/v	N	0x1	LF
D	8:0	BTDIV		Bt Div Bit time	divid	der [8:0]	l													r/v	N	0×1	FF

17.5 LINSB

LINS_ATHENS

					D	alasi	eet -
	LI	NSB DA	TABYTE03			0×5000	00060
		Dat	ta Bytes 0 to 3				
31 30	29 28	27 26 25 24	23 22 21 20 19 18 17 16	15 14 13 12 11 10 9 8	7 6 5 4	3 2	1 0
	А		В	С	I	D	
#	Bit(s)	Field	Description			Туре	Reset
Α	31:24	DATABYTE3	Data Byte 4 4th byte of the 8-byte Data Byte			r/w	0
В	23:16	DATABYTE2	Data Byte 3 3rd byte of the 8-byte Data Byte			r/w	0
С	15:8	DATABYTE1	Data Byte 2 2nd byte of the 8-byte Data Byte			r/w	0
D	7:0	DATABYTE0	Data Byte 1 1st byte of the 8-byte Data Byte			r/w	0

	LI	NSB DA	TABYTE47			0×5000	00064
		Dat	a Bytes 4 to 7				
31 30	29 28	27 26 25 24	23 22 21 20 19 18 17 16	15 14 13 12 11 10 9 8	7 6 5 4	3 2	1 0
	А		В	С		D	
#	Bit(s)	Field	Description			Туре	Reset
Α	31:24	DATABYTE7	Data Byte 7 8th byte of the 8-byte Data Byte			r/w	0
В	23:16	DATABYTE6	Data Byte 6 7th byte of the 8-byte Data Byte			r/w	0
С	15:8	DATABYTE5	Data Byte 5 6th byte of the 8-byte Data Byte			r/w	0
D	7:0	DATABYTE4	Data Byte 4 5th byte of the 8-byte Data Byte			r/w	0

	L	INSB	CS	SR																		0×5	5000	0068	8
			Coi	ntrol St	atus Regi	ster																			
31	30 29 28	27 26 2	5 24	23 2	2 21 2	9 19	18	17	16	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Α		В				С	D	E	F	G	Н	I	J	К	L	М	N	0	Р	Q	R	S	Т	U	
#	Bit(s)	Field			Descrip	tion																Ту	ре	Res	set
Α	31	ENHCHK				t con	trolle field clas	er has I sic cl	necks	sum		ieck	sum	type	e usee	d in t	he c	urrer	nt fra	ime b	у	r,	/w	0)
В	27:24	LENGTH			Data Le The hos frame b of the o	t con y adju	usting	g this	field	l. If t	this i	s loa	ded	with	the	value						r,	/w	0)
С	19	PARITY			Parity E		ity er	ror														r	0	0)

I				atasn	
#	Bit(s)	Field	Description	Туре	Reset
D	18	TIMEOUT	Timeout Error There are several reason that can cause a timeout error: The master detects a timeout error if it is expecting data from the bus but no slave does respond. If the slave responds to late and the frame is not finished within the maximum frame length TFRAME_MAX a timeout error will be detected too. The slave detects a timeout error if it is requesting a data acknowledge to the host controller (for selecting receive or transmit, data length and loading data), and the host controller does not set CTRL.DATA_ACK or CTRL.STOP register until the end of the reception of the first byte after the identifier. The slave detects a timeout error if it has transmitted a wakeup signal and it detects no sync field (from the master) within 150 ms. Note: The slave does not perform an exact check of the frame length TFRAME_MAX but a timeout is detected after 200 bit times, if the slave is in receive mode and there are missing data fields or a missing ID field from the master	ro	0
E	17	СНК	Checksum Error Checksum Error	ro	Θ
F	16	BITMON	Bit Error During Transmit: this gets set when the monitored state on the bus is different from the bit transmitted. During Receive: this gets set when detect a Byte Field Framing Error if the ninth bit after a valid start bit is dominant	ro	0
G	15	ACTIVE	Lin Bus Active The bit indicates whether the LIN bus is active or not. Note: For the LIN slave, this bit is set after the detection of a correct SYNC BREAK / SYNC FIELD sequence and it is reset at the end of the transmission or if the processing of the current frame is stopped by the host controller 0x0 — no Lin bus activity 0x1 — transmission on the LIN bus is active	ro	0
Н	14	BUSIDLETIMEOUT	BUS Idle Timeout This bit is set by the LIN core if CTRL.SLEEP register is not set and no bus activity is detected for 4s. In addition, an interrupt request to the host controller is generated in that case. After that, the host controller may assume that the LIN bus is in sleep mode and it has to set CTRL.SLEEP register of the LIN core	ro	0
I	13	ABORTED	This bit is set by the LIN core slave if a transmission is aborted after the beginning of the data field due to a timeout or bit error (caused e. g. by a new sync break after missing data bytes). The bit is also set if the processing of the current frame has been stopped by setting CTRL.STOP register. The bit is cleared by the LIN core after receiving a correct SYNC BREAK / SYNC FIELD sequence	ro	0
J	12	DATAREQ	Data Request The LIN core slave sets the bit after receiving the Identifier and requests an interrupt to the host controller. The host controller has to decode the Identifier to decide whether the current frame is a transmit or a receive operation. It has to adjust CTRL.TRANSMIT register and to load the data length. For transmit operations it has to load the data buffer too. After that the host controller has to set CTRL.DATA_ACK register	ro	0
K	11	INTR	Interupt Request The LIN core sets the bit when it requests an interrupt to the host controller. It has the same value as the interrupt output INTR. The bit has to be reset by the host controller by setting the bit CTRL.RST_INT register	ro	0
L	10	ERROR	Lin Error The LIN core sets the bit if an error has been detected (compare error register). The bit has to be reset by the host controller by setting the bit CTRL.RST_ERR register	ro	0
М	9	WAKEUP	The bit is set when the LIN core is transmitting a Wakeup signal or when the LIN core has received a Wakeup signal	ro	0
N	8	COMPLETE	The LIN core will set the bit after a transmission has been successfully finished and it will reset it at the start of a transmission	ro	0
0	7	STOP	The host controller of the LIN slave has set this register if it handles a data request interrupt and can not make use of the frame content with the received identifier(e.g. extended identifiers). For that case the LIN slave stops the processing of the LIN communication until the next SYNC BREAK is detected. A read access to this bit delivers always the value 0	WO	Θ
Р	6	SLEEP	Sleep Request The bit is used by the LIN core to determine whether the LIN bus is in Sleep Mode or not. The host controller has to set the bit after sending or receiving a Sleep Mode frame or if a bus idle timeout interrupt is requested. The bit will be reset by the LIN core when a wakeup signal is detected	r/w	0
Q	5	TRANSMIT	Transmit Operation The bit determines whether the current frame is a transmit frame or a receive frame for the LIN node. It has to be set by the host controller 0x0 — receive operation 0x1 — transmit operation	r/w	0

#	Bit(s)	Field	Description	Туре	Reset
R	4	DATAACK	Data Acknowledgement The bit has to be set by the host controller of a LIN slave after handling a data request interrupt (compare STATUS.DATA_REQ register). The bit will be reset by the LIN core	r/w	0
S	3	RSTINT	Reset interrupt The host controller has to set this bit to reset the STATUS.INTR register and the interrupt request output of the LIN core. A read access to this bit delivers always the value 0	WO	0
Т	2	RSTERR	Reset Error The host controller has to set this bit to reset the error bits in status register and error register. A read access to this bit delivers always the value 0	WO	0
U	1	WAKEUPREQ	WakeUp Request The bit has to be set by the host controller to terminate the Sleep Mode of the LIN bus by sending a Wakeup signal. The bit will be reset by the LIN core	r/w	0

			L	INSB	C	ONFIG																		0×5	000	0006	С
					Со	nfiguratio	on Re	gister																			
31	30	29	28	27 26	25 24	23 22	21	20	19 18	17	16	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
				Α	В				С			[)										Ε				
#	ŧ	Bit	t(s)	Field		Des	cripti	ion																Тур	е	Res	et
A	4	27:	26	BUSI	NACTIV	E Bus	Inact	ivity T	ïme															r/v	V	0	
Е	3	25:	24	WUPR	EPEAT	wak	eup r	epeat	time															r/v	V	0	
C	2	21:	16	ID		Fran	ne ID)																r/v	V	0	
С)	15:	14	PRES	CL		caler scaler	r Setti	ng															r/v	V	3	
E		8	: 0	BTDI	V	Bt D Bit t		divide	r															r/v	V	0×1	FF

		LINSB :	SYNCCOUNT	0×5	0000070
		5	sync counter Register		
31 36	29 28	27 26 25 2	4 23 22 21 20 19 18 17 16 15 14 13 12 11 10 9 8 7 6 5 A	4 3	2 1 0
#	Bit(s)	Field	Description	Туре	Reset
Α	17:0	SYNCCOUNT	sync counter number of clk_sys per sync pattern = sync count * (2^(PRESCL+1))	ro	0x3FFFF

17.6 BTE

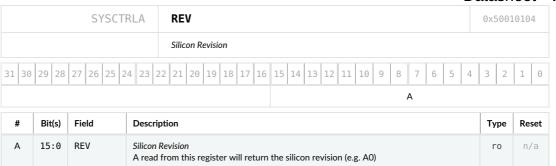
		В	ГΕ		B.	TE_	СТ	RL																			0×5	5000	008	0
					Th	is re	giste	l Reg er ca er wil	n on	ly b		ritten	if th	iere i	s no	ong	oing	trar	sfer	. If th	e B1	ΓE is	trans	ferri	ng da	ata, a	ıny w	rites	to	
31 30	29 2	8 2	27 2	6 2	25	24	23	22	21	20	19	18	17	16	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
			A E	3	С	D					E												F							
#	Bit(s)	Fiel	d			Des	crip	tion																		Ту	/pe	Res	set
Α	2	7	STA	RT				oper nplet		n is	initia	ated	wher	n this	s bit	is se	t. Ti	ne bit	aut	o-cle	ars v	wher	the	block	(is		r,	/W	0)
В	2	6	BLC	CK:	ING	ì	bus unt	, it w	ill st rem	all ı nain	until ider (the b	olock	tran	sfer	is co	mp	lete.	lf no	. If th ot set then	the	n the	e MC	U wa	aits o	nly	r	/W	G)
С	2	5	TX_	DI	R		Tra	nsfer	r dire	ecti	on. If	f set	then	SRA	M->	ASIC	ot	nerw	ise A	ASIC-	>SR.	AM					r,	/W	e)
D	2	4	INC	_A[DDR	t		et the				addre	ess ir	ncrer	nent	s at	the	end (of ea	ch tr	ansf	er. S	et to	zero	if th	е	r,	/W	G)
E	23:1	6	BXN	UM			Nur	nber	of 3	2-b	it wo	rds to	o trar	nsfer													r,	/W	G)
F	15:	0	BXA	DD								lie (LS bits (e AS	IC di	ie ad	dre:	ss. Th	ne M	ISBs a	are C)x50	01				r,	/W	0)

		ВТЕ	BTE_SRAM_A	ADDR												0×500	0008	4
			TE SRAM Addres	ss Register														
31 30	29 28	27 26 25	24 23 22 21	20 19 18	8 17 16	15 14	13	12 1	1 10	9	8	7	6	5	4	3 2	1	0
											,	4						
#	Bit(s)	Field	Description	1												Туре	Re	set
	1																	

17.7 SYSCTRLA

System control

		SYSCTE	RLA	NAME	0x5001	0100
				ASIC name		
31 30	29 28	27 26 25 2	24 23	22 21 20 19 18 17 16 15 14 13 12 11 10 9 8 7 6 5 4	3 2	1 0
				A		
#	Bit(s)	Field	Desc	ription	Туре	Reset
Α	31:0	NAME	ASIC A rea	name d from this register will return the ASIC name	ro	n/a



		SYSCTRL	A RETAIN	0×5001	.0108
			Retained data		
31 30	29 28	27 26 25 2	24 23 22 21 20 19 18 17 16 15 14 13 12 11 10 9 8 7 6 5 4 A	3 2	1 0
#	Bit(s)	Field	Description	Туре	Reset
Α	31:0	RETAIN	Firmware scratch register Only reset at power-on (e.g. contents retained in Hibernate mode and retained despite	r/w	0

	SY	SCTRLA	DEBUG	_ACCESS_KEY	0x5001	1010C
			Debug ac	cess key		
31 36	29 28	27 26 25	24 23 22	21 20 19 18 17 16 15 14 13 12 11 10 9 8 7 6 5 4 A	3 2	1 0
#	Bit(s)	Field		Description	Туре	Reset
	31:0	DEBUG ACC		Write the value 0x1dacce55 to this register to enable debug options. Write	r/w	0

	SY	SCTRLA	TRIM	_ACCESS_KEY	0×5001	10110
			Trim ac	ccess key		
31 30	29 28	27 26 25	24 23 2	22 21 20 19 18 17 16 15 14 13 12 11 10 9 8 7 6 5 4 A	3 2	1 0
#	Bit(s)	Field		Description	Туре	Reset
Α	31:0	TRIM_ACCE	SS_KEY	Write the value 0x1d155afe to this register to enable 'trim access' (which allows write access to various trim settings and production test options). Write any other value to disable trim access. [31:29] is used as tx1_pd_ena	r/w	0

																								L	ali	ası	lee	ι -
	SYSCT	ΓRLA		TR	IMC	CTR	L1																		0)	×500	L011	4
				trim	regi	sters	for l	oand	gaps,	, regi	ula	tors, (oscilla	tors														
31 30	29 28	27 26	25	24	23	22	21	20	19	18	1	7 16	15	14	13	3 12	11	10	9	8	7	6	5	4	3	2	1	0
	Α									В					С				D				E				F	
#	Bit(s)	Field				Des	scrip	tion																	1	Гуре	Res	set
Α	31:24	HF0S	С									quenc acce			oled											r/w	0×	FF
В	20:16	LF0S	С									uenc acce			oled											r/w	0×	1F
С	14:12	VC0R	E_MC	CU					_			oltag acce														r/w	2	2
D	11:8	VC0R	E_MC	CU_C	Z				_			ompe acce			•	itor t	rim									r/w	6	;
E	6:4	VBGV	REG			Trir	n fo	ndgap r the only,	vreg	g bar	•	gap acce	ss' is e	enak	oled											r/w	2	<u>}</u>
F	2:0	VBG				Trir	n fo	trim the only,	maiı			gap acce	ss' is e	enak	oled											r/w	4	ŀ

		SYS	CTRLA		TR:	IMCTI	RL2																	0×	5001	10118
				1	trim	registe	rs for	spea	kers, Iz	TC																
31	30	29 28	27 26	25 2	4 2	23 22	21	20	19 1	8 17	16	15	14	13	12	11	10	9	8	7	6	5	5 4	3	2	1 0
			A	4					E	3							С				ı	D				E
#		Bit(s)	Field		ı	Descrip	tion																	T-	уре	Reset
A		27:24	PGA12	2LPF		trim valı — read-					ss' is e	enabl	ed											r	/W	0
В		20:16	IZTCN	NEG		trim valı — read-				acces	ss' is e	enabl	ed											r	/W	0x13
С		12:8	IZTCF	P0S		trim valı — read-				acces	ss' is e	enabl	ed											r	/W	0×11
D		7:4	SPKR2	2	9	speaker. speaker – read-	2 tri	m	s 'trim	acces	ss' is e	enabl	ed											r	/W	4
E		3:0	SPKR1	1	9	speaker speaker – read-	1 tri	m	ss 'trim	acces	ss' is e	enabl	ed											r	/W	4

	SYSC	TRLA US	TRXDFT	0×5001	1011C
		ultro	asound transceiver driver direct control		
31 30	29 28	27 26 25 24	23 22 21 20 19 18 17 16 15 14 13 12 11 10 9 8 7 6 5 4	3 2	1 0
			АВ		С
#	Bit(s)	Field	Description	Туре	Reset
Α	8	USTRXADCOUT	Output ADC words When selected, envelope FIFO is loaded with ADC results — read-only, unless 'debug access' is enabled	r/w	0
В	4	USTRXFRCENA	Enable for direct drive control Enable for direct drive control — read-only, unless 'debug access' is enabled	r/w	0
С	3:0	USTRXFRCDRV	Drive levels to apply when transmit direct drive enabled Drive levels to apply when transmit direct drive enabled. [3]: TX1P, [2]: TX2P, [1]: TX1N, [0]: TX2N - read-only, unless 'debug access' is enabled	r/w	0

	SYSCT	RLA ANA	TEST	0×5	001	0120
		vario	is testmodes to test analog frontend			
31 30	29 28	27 26 25 24 2	23 22 21 20 19 18 17 16 15 14 13 12 11 10 9 8 7 6 5 4	3	2	1 0
			A B C D E F	G	Н	I
#	Bit(s)	Field	Description	Ту	ре	Reset
Α	12	VBGBUF	Buffered VBG test enable — read-only, unless 'debug access' is enabled	r/	W	0
В	11:10	USTXTESTENA	kelvin sensing tx pin test bits test bits for kelvin sensing on TX pin — read-only, unless 'debug access' is enabled	r/	W	0
С	9	GPADCCON	connect all GPIOs to ADCIN net forces all the GPIOs(PAs & PBs) to connect to the ADC input. can be used for VIL/VIH testing — read-only, unless 'debug access' is enabled	r/	W	0
D	8	REFOSC	reference oscillator test enable — read-only, unless 'debug access' is enabled	r/	W	Θ
E	7:6	USRXTESTENA	drives the usrx_test_ena — read-only, unless 'debug access' is enabled	r/	W	0
F	5:4	TXCP	TX charge-pump test enable TODO — read-only, unless 'debug access' is enabled	r/	W	0
G	3	VBG	vbg test enable — read-only, unless 'debug access' is enabled	r/	W	0
Н	2	VBGVREG	vbg vref test enable — read-only, unless 'debug access' is enabled	r/	W	0

0x0 — Not in testmode, pos_ena and neg_ena controlled by core

17.8 CRGA

Clock & reset generator

1:0

IZTC

iztc test mode selection Selects the mode to be tested

0x1 — only neg_ena set
0x2 — only pos_ena set

- read-only, unless 'debug access' is enabled

0x3- force pos_ena and neg_ena '1

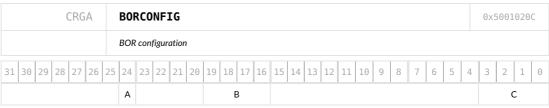
		CRGA	CLOC	KSRC	0×500	1020	0
			Low fre	quency clock control			
31 30	29 28	27 26	25 24 2:	3 22 21 20 19 18 17 16 15 14 13 12 11 10 9 8 7 6 5 4	3 2	1	0
				A B		С	D
#	Bit(s)	Field		Description	Туре	Res	set
Α	9	ACTIVES	SYSCLK	active system clock tells abouts the clock being used as system clock $0x \textbf{0} - \text{Slow clock } 10 \text{kHz} \\ 0x \textbf{1} - \text{Fast clock } 16 \text{MHz}$	ro	n/	'a
В	8	SYSCLK	SEL	System clock select selects the clock between fast and slow system clocks $0x0 - \text{Slow clock (10kHz)}$ $0x1 - \text{Fast clock (16MHz)}$	r/w	6)
С	1	HFRCST!	S	Fast RC oscillator status Will be high if the 16MHz RC oscillator is enabled	ro	6)
D	0	HFRCEN	A	Fast RC oscillator enable Setting this bit enables the 16MHz RC oscillator	r/w	e)

r/w

															טט	ala	SH	CC	ι -
		CRGA	RES	SETCTRL												0×5	5001	020	4
			Rese	t control															
31 30	29 28	27 26	25 24	23 22 21	20 19 18 17	16	15 14 13	12	11	10	9	3 7	6	5	4	3	2	1	0
			А			В		С	D		Е	F			G	Н		ı	J
#	Bit(s)	Field		Descriptio	n											Ту	ре	Res	set
Α	24	REQ		Hard reset	request											W	10	0)

#	Bit(s)	Field	Description	Туре	Reset
Α	24	REQ	Hard reset request Set to trigger a hard reset of Brock	WO	0
В	16	REQ	Soft reset request Set to trigger a soft reset of Brock — cleared automatically after each write	WO	0
С	12	WDTA	WDT flag clear Set to clear the WDT flag	WO	0
D	11	BORVCORE_MCU	BOR VCORE_MCU clear Set to clear the 1.8V brownout detected flag	WO	0
E	9	BORVDDA	BOR VDDA clear Set to clear the VDDA brownout detected flag	WO	0
F	8	POR	POR flag clear Set to clear the POR flag	WO	0
G	4	WDTA	Watchdog bark flag Set by the hardware when the watchdog barks	ro	n/a
Н	3	BORVCORE_MCU	BOR VCORE_MCU flag Set by the hardware when a brownout of the 1.5V supply is detected	ro	0
I	1	BORVDDA	BOR VDDA flag Set by the hardware when a brownout of the VDDA supply is detected	ro	0
J	Θ	POR	Power on reset flag Set by the hardware during power-on reset	ro	n/a

		CRGA	ВО	RACT	ION																	0x!	5001	.020	8
			ВО	R actio	1																				
31 30	29 28	27 26	25 24	23 2	22 21	20	19 18	3 17	16	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
																					Α			E	В
#	Bit(s)	Field		Descr	iption																	Ту	/pe	Re	set
А	5:4	VCORE_	MCU	Define detect 0x 0x	CORE_es the coted by the color of the color	consequent the had action Q gene	uence dware n erated	e		n-ou	t cor	iditi	on o	n the	e VC	ORE.	_MC	U su	pply	bein	g	r,	/W	2	2
В	1:0	VDDA		Define by the 0x	/DDA a es the c e hardw c0 — No e1 — IRe e2 — Ha	consequate vare of action Q general	n erated			n-ou	t cor	nditio	on o	n the	è VDI	DA s	uppl	ly bei	ing d	etec	ted	r	/W	Ź	2



			Α			В							С
#	Bit(s)	Field			Desci	ription						Туре	Reset
Α	24	B0RTESTE	ENA			test enable ly accessible when	ʻdebug a	ccess' is en	abled			r/w	0
В	19:16	BORVCORE	EMCU	THRESH	Select	VCORE_MCU thre t the BOR thresh x0 - 1.212V x1 - 1.227V x2 - 1.243V x3 - 1.259V x4 - 1.275V x5 - 1.292V x6 - 1.310V x7 - 1.328V x8 - 1.346V x9 - 1.365V xa - 1.385V xb - 1.405V xc - 1.426V xd - 1.447V xe - 1.469V xf - 1.491V		ige level fo	r the VCOI	RE_MCU re	gulator	r/w	8
C	3:0	BORVDDAT	THRE	SH	Select 0: 0: 0: 0: 0: 0: 0: 0: 0: 0: 0: 0: 0:	VDDA threshold t the BOR threshold tthe BOR threshold x0 - 1.61V. DVT x1 - 1.65V. DVT x2 - 1.69V. DVT x3 - 1.73V. DVT x4 - 1.77V. DVT x5 - 1.82V. DVT x6 - 1.87V. DVT x7 - 1.92V. DVT x8 - 1.98V. DVT x9 - 2.04V. DVT xa - 2.10V. DVT xc - 2.24V. DVT xc - 2.24V. DVT xd - 2.40V. DVT xe - 2.58V. DVT xf - 2.79V. DVT	data dis	agrees. TB		A regulator		r/w	θхС

		CRGA	WDTACTION	0×500	1021	0
			WDT action			
1 30	29 28	27 26 2	5 24 23 22 21 20 19 18 17 16 15 14 13 12 11 10 9 8 7 6 5 4	3 2	1	0
Ċ						Δ
#	Bit(s)	Field	Description	Туре	Res	set

17.9 PMUA

Power management unit

				PMUA		C.	TR	L																			0>	5001	1030	0
						Со	ntr	rol																						
31	30	29 2	8	27 26	25	24	2	3 22	21	2	20 19	18	17	7 1	.6 15	14	1	.3 12	11	10	9	8	7	6	5		1 3	2	1	0
																												Α	В	С
#		Bit(s)		Field				Des	cripti	ioi	n																Т	уре	Re	eset
А		2		FASTSI	HUTI	1WOC	N	Whe fast Hav	oscil ing th	t, lat	the Pl tor du fast c	ring p scilla	owe tor i	er c	le-esc	alatio I this	n i oi	n of the when ption s ble	ente	ring t	he	Hibe	nate	state	<u>.</u>		:	~/W		1
В		1		FASTB	00T			Set to	uding gs th	ab g t	he po systen	rtion n up v	con: with	sur	ned by e slow	the	Clo k t	subse ough l o mak e as po	oot e the	sequ initi	enc	ce). Tl	e de	fault	valı			-/W		1
С	:	0		HIBERI	NATI	E		inte	rupt	C		er H	OLD) bi				efore s t (and		_						е		WO		0

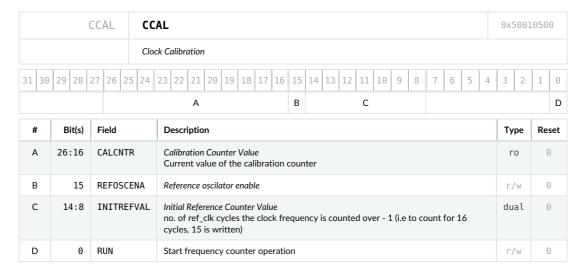
		PMUA DE	BUG	0x500	10304
31 30	29 28	27 26 25 24	23 22 21 20 19 18 17 16 15 14 13 12 11 10 9 8 7 6 5 4	3 2	1 0
					Α
#	Bit(s)	Field	Description	Туре	Reset
	I				

17.10 EVTHOLD

Event hold



17.11 CCAL



	С	CAL I	RQ	0×5001	10504
			CAL interrupts ontains the enable, clear, status and active flags for the CCAL interrupt sources.		
31 30	29 28	27 26 25	24 23 22 21 20 19 18 17 16 15 14 13 12 11 10 9 8 7 6 5 4	3 2	1 0
			A B C		D
#	Bit(s)	Field	Description	Туре	Reset
Α	24	CCAL	calibration completed inpterrupt active	ro	0
В	16	CCAL	calibration completed interrupt status	ro	0
С	8	CCAL	calibration completed interrupt clear — cleared automatically after each write	WO	0
D	0	CCAL	calibration completed interrupt enable	r/w	0

17.12 IOCTRLA

I/O control

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]	0C	TF	RLA			GP	A	P	L																										0×	500	L06	500
							GPI	0	P	ort .	A L	.ow	er	Nil	oble	Pin	Со	ontr	ol																				
31 30	29	28	2	7 2	5	25	24		23	2	2	21	2	20	19	18	3	17	16	15	1	4	13	12	1	1	10	9)	8	7	6	5	5	4	3	2	1	L
		A	E	+	+		D			-	-		H	E	F	G	÷	F			-	.		1	ر ا	+	K		L						М	N	0		P
#	В	it(s)	Ī	Field	d				Dε	scr	ipt	ion	_																								ype	F	Rese
Α		28		PDE	NA	3					-			ı eı	nable	3																					/W		0
		27		DUE		_										GP/	4[3	3]																					0
В		27		PUE	NA	.3						lup Pullu				A[3]																			,	/W		0
С		26		RDE	NA	3						d ei Read				GP	·Α[[3]																		r	/W		0
D		24		HWM	0D	E3									ode	ode	00		2100	1																r	/W		0
									-11											DA E	ari	um	set	ting	S														
										0>	1	– P	Ά	3 ι	sed	to c	out	tput	t PV	/M																			
E		20		PDE	NA	2									nable on	e GPA	۹[2	2]																		r	/W		0
F		19		PUE	NA	2						lup Pulli				A[2]]																			r	/W		0
G		18		RDE	NA	2						d ei				ı GP	ΊΑ	2]																		r	/W		0
Н	17	:16		HWM	0D	E2									ode	ode			2100	1																r	/W		0
									-11										-) DA b	ari	um	set	ting	S														
																as I																							
																for for				D Lou	tpu	t																	
ı		12		PDE	NA	1									nab on	le GPA	۹[1	1]																		r	/W		0
J		11		PUE	NA	1						lup Pulli				A[1]]																			r	/W		0
К		10		RDE	NA	1						d ei Read				ı GP	'A[[1]																		r	/W		0
L	,	9:8		HWM	0D	E1									ode	ode	on	G	ΡΔ[1	1																r	/W		0
																			-	DA E	ari	um	set	ting	S														
																as I				ut																			
																for for) ou	tpu	t																	
М		4		PDE	NA	.0				0	pul	Ido	wn	ı eı	nable	2																				r	/W		0
N		3		PUE	NA	0		F	Pir	0	pul	lup	en	nab	le	GP/		נע																		r	/W		0
0		2		RDE	NA	0		F	Pir	0 1	rea	d e	nai	ble		A[0]																				r	/W		0
P		1:0		HWM	0D	E0									h or node	i GP	ΑĮ	.UJ																		r	/W		0
		-			-					abl	e F	laro	wb	/ar	e m	ode			-)] DA E	ari	um	set	tino	S														
																as I					-uil	a111	JUL	. e	,														
										0>	⟨2 ⋅	– P	Α	0 ι	sed	for	UA	4RT	TX	D																			

0x3 - PA0 used for UART RXD

				aia	J11	CC	-
	IOC	CTRLA G	GPAPU	0×5	001	0604	ŀ
		G	SPIO Port A Upper Nibble Pins Control				
31 30	29 28	27 26 25 2	4 23 22 21 20 19 18 17 16 15 14 13 12 11 10 9 8 7 6 5 4	3	2	1	0
			A	В	С		D
#	Bit(s)	Field	Description	Ту	ре	Res	et
Α	4	PDENA4	Pin 4 pulldown enable Enable Pulldown on GPA[4]	r/	/W	0	
В	3	PUENA4	Pin 4 pullup enable Enable Pullup on GPA[4]	r/	/W	0	
С	2	RDENA4	Pin 4 read enable Enable Read path on GPA[4]	r/	/W	0	
D	0	HWMODE4	Pin 4 hardware mode Enable Hardware mode on GPA[4] 0x0 — PA4 controlled by GPIOA barium settings 0x1 — PA4 used for UART TXD	r/	/W	Θ	

	IOC	TRLA G	PBPL	•																	0×1	5001	.060	8
		Gi	PIO Po	rt B L	.ower Nil	oble	Pins C	ontrol																
31 30	29 28	27 26 25 24	4 23	22	21 20	19	18	17 16	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
			Α	В	С	D		E	F	G		Н	ı			J	К	L		М	N			0
#	Bit(s)	Field	Desc	riptio	on																Ту	/ре	Re	set
Α	23	LVL2	Pin 2	level																	r,	/W	(9
В	22	STR2	Pin 2	strer	ngth																r,	/W	(9
С	20	PDENA2	Pin 2	pulla	lown ena	ble															r,	/W	(9
D	19	PUENA2	Pin 2	pullu	ıp enable																r,	/W	(9
E	16	HWMODE2	Enab 0	le Ha x 0 –	ware mo ardware PB2 coi PB2 use	mod ntrol	led by	GPIO.		ium	setti	ngs									r,	/w	(9
F	15	LVL1	Pin 1	level																	r,	/W	(9
G	14	STR1	Pin 1	strer	ngth																r,	/W	(9
Н	12	PDENA1	Pin 1	pulla	lown ena	ble															r,	/W	(9
1	11	PUENA1	Pin 1	pullu	ıp enable																r,	/W	(9
J	8	HWMODE1	Enab 0	le Ha x 0 –	ware mo ardware PB1 coi PB1 use	mod ntrol	led by	GPIO		ium :	setti	ngs									r	/w	(9
К	7	LVL0	Pin 0	level																	r,	/W	(9
L	6	STR0	Pin 0	strer	ngth																r,	/W	(9
М	4	PDENA0	Pin 0	pulla	lown ena	ble															r,	/W	(9
N	3	PUENA0	Pin 0	pullu	ıp enable																r,	/W	(9
0	Θ	HWMODE0	Enab 0	le Ha x 0 –	ware mo ardware PBO coi PBO use	mod ntrol	led by	GPIO.		ium	setti	ngs									r	/W	(9

#	Bit(s)	Field		Descript	on															Ту	ре	Res	set
															Α								В
31 30	29 28	27 26 25	24	23 22 2	1 20	19 18	17 3	16 15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
				Debug M	ode En	ables																	
		IOCTRL/	4	DEBUG	ENA															0×5	001	060	С
																					J11	-	•

#	Bit(s)	Field	Description	Туре	Reset
А	8	EFUSEEXTENA	enable driving the fuse macro externally this enables fuse macro driven via following pins. PBO: resetn, PAO: clk1, PA1: clk2, PA2: pw — only accessible when 'debug access' is enabled	r/w	0
В	0	EXTCLKENA	external clock enable This needs to be set if PA1 needs to be used as an external clock source to replace the high frequency RC, This should only be set if GPAPL.HWMODE1 is 0, and GPAPL.RDENA1 is set — only accessible when 'debug access' is enabled	r/w	0

		IOCTRLA	LINMUX								0×5	5001	0610)
			LIN Bypass Control											
31 30	29 28	27 26 25 2	23 22 21 20 19 18 17 1	6 15 14 13 12 1	.1 10	9	8	6	5	4	3	2	1	0
							А							В
#	Bit(s)	Field	Description								Ту	ре	Res	et
Α	8	RPTRENA	LIN repeater enable TODO								r	/W	0	
												/w	(-)	

			IOC	TRLA		GP	LIN																		0×5	5001	.061	4
						LIN	Pin C	Contr	ol																			
31 30	29	28	27 26	25 24	23	22	21	20	19	18	1	17 16	15	14	13	12	11	16	9	8	7	6	5	4	3	2	1	0
A		В	С	D	E	F	G	Н	ı	J		K	ı			М	ı	N		0	Р	Q	R	S	Т	U	١	V
#	В	it(s)	Field		De	scrip	otion																		Ту	pe	Res	set
Α	31	:30	SPKF	RISEL1	LIN	12 sp	kr ise	ıl																	r,	/w	0	9
В		28	DIAG	PD1	LIN	12 di	agnos	stic p	ulldo	own (en	able													r,	/w	0	9
С	27	:26	TXIF	PD1								strengt cess' is e		led											r,	/W	0	Э
D	25	:24	TXSL	.EW1			0x1 0x2 0x3) — ~ L — ~ 2 — ~	∙5 us •0.6 •50 r •3 ns	us ns		cess' is o	enabl	led											r,	/w	6	•
E		23	TXPC	L1	LIN	12 tro	ansmi	it po	larity	/															r,	/w	0	9
F		22	RXPC	L1	LIN	12 re	ceive	pola	rity																r,	/w	0	9
G		21	MPU1	.K1			aster laster					able													r,	/W	6	9
Н		20	SPU3	80K1			ave P ave F				ena	able													r,	/w	0	Э
1		19	BIAS	ENA1			as en the		for	the L	LIN	N2 tran	sceiv	ver											r	/w	0	9

			De	atasn	ieei .
#	Bit(s)	Field	Description	Туре	Reset
J	18	RDENA1	LIN2 receive enable Enable receive path on LIN2, this is independent of HWMODE1, make sure this is set when expecting input data from LIN1	r/w	0
К	17:16	HWMODE1	LIN2 hardware mode select the HW mode on LIN2 0x0 — LIN2 DATA/TX_ENA controlled by GPIOA barium settings 0x1 — LIN2 used to connect the lin controller 0x2 — LIN2 used for uart, lin2_rxd conneects to uart_rxd and uart_txd connects to lin2_txd. if HWMODE0 is set lin2_rxd conneects to uart_rxd only 0x3 — LIN2 used to output PWM	r/w	1
L	15:14	SPKRISEL0	LIN1 spkr isel	r/w	0
М	12	DIAGPD0	LIN1 diagnostic pulldown enable	r/w	0
N	11:10	TXIPD0	LIN1 Transmitter pull-down strength — read-only, unless 'trim access' is enabled	r/w	0
0	9:8	TXSLEWO	LIN1 Transmitter slew select $0x05$ us $0x10.6$ us $0x250$ ns $0x33$ ns $-$ read-only, unless 'trim access' is enabled	r/w	0
Р	7	TXP0L0	LIN1 transmit polarity	r/w	0
Q	6	RXP0L0	LIN1 receive polarity	r/w	0
R	5	MPU1K0	LIN1 Master Pullup Enable LIN1 Master Pullup(1K) enable	r/w	0
S	4	SPU30K0	LIN1 Slave Pullup Enable LIN1 Slave Pullup(30K) enable	r/w	0
Т	3	BIASENA0	LIN1 Bias enable enables the Bias for the LIN1 transceiver	r/w	0
U	2	RDENA0	LIN1 receive enable Enable receive path on LIN1, this is independent of HWMODE0, make sure this is set when expecting input data from LIN1, for example when HWMODE0 is set to 2, still you need to set this bit to enable the receive path	r/w	0
V	1:0	HWMODEO	LIN1 hardware mode select the HW mode on LIN1 0x0 — LIN1 DATA/TX_ENA controlled by GPIOA barium settings 0x1 — LIN1 used to connect the lin controller 0x2 — LIN1 used for uart, lin1_rxd connects to uart_rxd and uart_txd connects to lin1_txd. if HWMODE1 is set uart_txd connects to lin1_txd only 0x3 — LIN1 used to output PWM	r/w	1

				atasi	
	IOCT	RLA LI	INIDLYCOMP	0x5001	10618
		LIN	N1 Delay compensation control		
31 30	29 28	27 26 25 24	23 22 21 20 19 18 17 16 15 14 13 12 11 10 9 8 7 6 5 4	3 2	1 0
А		В	C D	E F	G H
#	Bit(s)	Field	Description	Туре	Reset
Α	31	DCEDG	LIN1 delay compensation edge	dual	0
В	30:24	DCVAL	LIN1 delay compensation value	dual	0
С	22:16	DMF	LIN1 measured fall edge delay	ro	0
D	14:8	DMR	LIN1 measured rise edge delay	ro	0
E	3	DCE	Enable LIN1 Delay compensation	r/w	0
F	2	DME	Enable LIN1 Delay Measurement	r/w	0
G	1	ACE	Enable LIN1 AUTO Delay compensation measures delays and updates the comp registers. ignores the DME and DCE settings. updates DCEDG and DCVAL automatically after every measurement	r/w	0
Н	Θ	ВҮР	Enable bypass pass through the drive without any synchronous delay	r/w	0

	IOC	TRLA LI	N2DLYCOMP	0×5	С						
		LIN	11 Delay compensation control								
31	30 29 28	27 26 25 24	23 22 21 20 19 18 17 16 15 14 13 12 11 10 9 8 7 6 5 4	3	2	1	0				
Α		В	C D	Ε	F	G	Н				
#	Bit(s)	Field	Description	ре	Res	set					
А	31	DCEDG	LIN2 delay compensation edge	2 delay compensation edge dua							
В	30:24	DCVAL	LIN2 delay compensation value	dual		0)				
С	22:16	DMF	LIN2 measured fall edge delay	r	ro		9				
D	14:8	DMR	LIN2 measured rise edge delay	r	0	0)				
Е	3	DCE	Enable LIN2 Delay compensation	r/	W	0)				
F	2	DME	Enable LIN2 Delay Measurement	r/	W	0)				
G	1	ACE	Enable LIN2 AUTO Delay compensation measures delays and updates the comp registers. ignores the DME and DCE settings. updates DCEDG and DCVAL automatically after every measurement	r/	'W	e)				
Н	0	ВҮР	Enable bypass pass through the drive without any synchronous delay	r/	'W	G)				

IOCTRLA	LINTMODE								0×5	0010	0620
	LIN Test Mode Control										
31 30 29 28 27 26 25 24	23 22 21 20 19 18 17 16 15 14 13	12	11 10	9	8	7 6	5	4	3	2	1 0
		Α			В			С			D

#	Bit(s)	Field	Description	Туре	Reset
А	12	GPACON1	LIN2 test via GPA If set to '1 it connects the lin2_txd to PA[0] and lin2_rxd to PA[1]. This only works if GPAPL.HWMODO and GPAPL.HWMOD1 is set to 0. GPLIN.HWMODE1 should be set to '0, The LIN2 receive path needs to be set via GPLIN.RDENA1, The rest of the port directions gets automatically set — only accessible when 'debug access' is enabled	r/w	Θ
В	8	DIGINTEST1	Enable LIN2 Digital Test Input If set to '1 it enables the digital test input path. GPLIN.BIASENA1 needs to be set to allow this debug feature — only accessible when 'debug access' is enabled	r/w	0
С	4	GPACON0	LIN1 test via GPA If set to '1 it connects the lin1_txd to PA[0] and lin1_rxd to PA[1]. This only works if GPAPL.HWMOD0 and GPAPL.HWMOD1 is set to 0. GPLIN.HWMODE0 should be set to '0, The LIN1 receive path needs to be set via GPLIN.RDENA0, The rest of the port directions gets automatically set — only accessible when 'debug access' is enabled	r/w	0
D	0	DIGINTEST0	Enable LIN1 Digital Test Input If set to '1 it enables the digital test input path. GPLIN.BIASENAO needs to be set to allow this debug feature — only accessible when 'debug access' is enabled	r/w	0

	:	IOCTRLA	DIGTESTMUX				0×500	10624
			Digital test mux select					
31 30	29 28	27 26 25 2	4 23 22 21 20 19 18 17 16 15 14	13 12 11 10 9 8	7 6	5 4	3 2	1 0
				Α			В	
#	Bit(s)	Field	Description	A			Туре	Reset

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В	it(s) Fi	eld	Description	Туре	Reset
5	5:0 TE	ESTMUXSEL0	Selects debug signal to output on port A pin 1	r/w	0
			0x 0 — ustrx: dftmux_cmp		
			0x1 — ioctrla: a_lin1_itrx_pd		
			0x2 — ioctrla: a_lin2_itrx_pd		
			0x3 — ioctrla: a_lin1_itrx_pd_dly		
			0x4 — ioctria: a_lin2_itrx_pd_dly		
			0x5 — ioctria: a_lin1_dig_in		
			0x6 — ioctria: a_lin2_dig_in		
			0x7 – hkadc: adc_clk		
			0x8 - hkadc: state[0]		
			0x9 - hkadc: state[1]		
			Oxa — hkadc: state[2]		
			0xb — ccal: ref_clk		
			0xc — efuse: pw		
			0xd — efuse: reset_n		
			Oxe — efuse: clk1		
			Oxf — efuse: clk2		
			0x10 — efuse: state[0]		
			0x11 – efuse: state[1]		
			0x12 – efuse: state[2]		
			0x13 – efuse: state[3]		
			0x 14 – efuse: 1'b0		
			0x15 — efuse: bit_count[0]		
			0x16 – efuse: bit_count[1]		
			0x17 – efuse: bit_count[2]		
			0x18 — efuse: bit_count[3]		
			0x19 — efuse: bit_count[4]		
			0x1a — efuse: bit_count[5]		
			0x 1b — efuse: end_wait_pulse		
			0x 1c – linm: rxd		
			0x 1d – linm: txd		
			0x 1e − lins: rxd		
			0x1f – lins: txd		
			0x20 — crga: clk_lf_rc		
			0x 21 – crga: clk_hf_rc		
			0x22 — crga: clk_lf_ext (external clk only observed on GPA2)		
			0x23 — crga: clk_sys_gated		
			0x 24 — crga: a_por_n		
			0x 25 — crga: bor_vdda_n		
			0x 26 — crga: bor_vcore_mcu_n		
			0x 27 — crga: wdt_bark		
			0x 28 — pmua: cstate[0]		
			0x 29 — pmua: cstate[1]		
			0x 2a — pmua: cstate[2]		
			0x 2b — pmua: cstate[3]		
			0x2c — pmua: counter[0]		
			0x 2d – pmua: counter[1]		
			0x 2e — pmua: counter[2]		
			0x2f — pmua: counter[3]		
			0x 30 — pmua: quacks		
			0x 31 — pmua: daffodil		
			0x32 – pmua: snowflake		
			only accessible when 'debug access' is enabled		

#	Bit(s)	Field	Description	Туре	Reset	
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17.13 WDTA

Watchdog Timer (barium)

	1	WDTA	СТ	RL																					0×	5001	.070	90
			Cor	ntrol																								
31 30	29 28	27 26 25	24	23 2	2 2	1 20	9 19	18	17	16	15	14	13	3 12	2 11	1 1	.0	9	8		7	6	5	4	3	2	1	0
			Α					Е	3	С									D								Ε	
#	Bit(s)	Field		Des	cript	tion																			Ty	/pe	Rese	
Α	24	WUPTOUT			g th		ner sto dicate		keup	tim	neout	eve	nt	has h	napp	ene	d. v	vrit	e a	'1 to	o cl	ear t	his		r	/W		0
В									r	r/w		3																
С	16	WUPTENA					keup ; the w			m h	iberi	nate	via	time	out	feat	ure	•							r/w			0
D	9:8	TIMEOUT	SEL	Def nex	This enables the wakeup from hibernate via timeout feature Timeout select Defines the watchdog timeout period (the time between a clear operation and the next timeout) $0x0 - 2^8$ * Strobe Period (25.6ms for 10kHz Strobe) $0x1 - 2^{10}$ * Strobe Period (102.4ms for 10kHz Strobe) $0x2 - 2^{13}$ * Strobe Period (819.2ms for 10kHz Strobe) $0x3 - 2^{17}$ * Strobe Period (13.1ms for 10kHz Strobe)									r		3												
Е	1	RUNNING		A fla	ag th 0x 0 -	– Wa	s dicate atchde atchde	og tin	ner i	s sto	oppe	d an				bled	l								r	⁻ 0		0

		WDTA	STOP	0×5001	L0704
31 30	29 28	27 26 25 2	24 23 22 21 20 19 18 17 16 15 14 13 12 11 10 9 8 7 6 5 4	3 2	1 0
			A		
#	Bit(s)	Field	Description	Туре	Reset

		WDTA	CLEAR	0×5001	.0708
31 36	29 28	27 26 25	24 23 22 21 20 19 18 17 16 15 14 13 12 11 10 9 8 7 6 5 4	3 2	1 0
	i	i	A	i	
#	Bit(s)	Field	Description	Туре	Reset
	31:0	CLEAR	Write the values 0x3c570001 and 0x007f4ad6 (in sequence, with no intervening	WO	0

	1	WDTA	CNTVAL	0×5001	.070C
			Counter value		
31 30	29 28	27 26 2	5 24 23 22 21 20 19 18 17 16 15 14 13 12 11 10 9 8 7 6 5 4	3 2	1 0
#	Bit(s)	Field	Description	Туре	Reset
Α	31:0	CNTVAL	Counter value The instantaneous value of watchdog timeout counter	ro	0

17.14 EFUSE_CTRL_HELIUM

eFUSE Controller

EEL	ICE CTI	RL HELIUM	CONF	0×5001	10000			
LIC	eFUSE configure register This register defines the timing of the signals used to program and read the efuse. Th needs to be adjusted to match the efuse signal spec. PROG_WIDTH defines the PW T1_T2 defines the hold/setup delays between CLK1 and PW. The Tclk period of both CLK2 is: Tclk = (PROG_WIDTH + (2 x T1_T2)).							
31 30	29 28	27 26 25 24	23 22 21 20 19 18 17 16 15 14 13 12 11 10 9 8 7 6 5 4	3 2	1 0			
#	Bit(s)	Field	Description	Туре	Reset			
A	23:16	T1_T2	Define the number of system clock cycles the T1 (hold time between CLK1 and PW) delay will be. The same register also is used to define the T2 delay (setup time between PW and CLK1). This register will allow the user to change the system clock frequency and keep being able to program the eFUSE macro. The number in this field multiply by the period of the system clock MUST be greater than 1us. The	r/w	0×10			
			reset value is set to work with the 16Mhz RC clock which is the default system clock					

Е	EFUSE_CTRL_HELIUM CTRL								0x50010804			
			Control of the opperations of the eFUSE Macro									
31 30	29 28	27 26 25 2	4 23 22 21 20 19 18 17 16 15 14 13 12 11 10 9	8	7	6 5	4	3	2	1	0	
				Α							В	
#	Bit(s)	Field	Description					Ту	/ре	Res	set	
Α	8	READ	Writting a one to this bit will start the read of the eFUSE macro dat DATA register(s). When the read operation is done, the controller velocities when the total controller with the DATA register(s)					r	/W	Э)	

				Dui	.uJi	CCL
	EFUSE	E_CTRL_HE	LIUM DATA	0	x5001	10808
			set 0 of 32-bit Data of the eFUSE Macro			
31 30	29 28	27 26 25	24 23 22 21 20 19 18 17 16 15 14 13 12 11 10 9 8 7 6 5	4 3	3 2	1 6
			Α			
#	Bit(s)	Field	Description		Туре	Reset
А	31:0	DATA	On read, this register return the value of the specific 32-bit of the eFUSE macro. On write, the value written is used to program the specific 32-bit of the eFUSE macro. T programming can only be done to set a bit to one. The programming can only be don during manufacturing. This register becomes a read only register once the chip used the application/field	e	r/w	0

EFU	JSE_CT	RL_HELIUM	DEBUG	0×500	1080C
			eFUSE debug register This register should only be used for debug. The Quasi programming feature is not in HW but it can be done by FW through this debug register.	mplemer	ıted in
31 30	29 28	27 26 25 24	23 22 21 20 19 18 17 16 15 14 13 12 11 10 9 8 7 6 5 4	3 2	1 0
			A B C D E		F
#	Bit(s)	Field	Description	Туре	Reset
Α	9:8	RD_THRES	set the read threshold for margin tests $0x0$ — threshold set for nominal read $0x1$ — threshold set for margin0 read $0x2$ — threshold set for margin1 read	r/w	0
В	7	PW_FW	When set, Firmware has control over the PW pin of the macro	r/w	0
С	6	CLK2_FW	When set, Firmware has control over the CLK2 pin of the macro	r/w	0
D	5	CLK1_FW	When set, Firmware has control over the CLK1 pin of the macro	r/w	0
E	4	RESETN_FW	When set, Firmware has control over the RESETN pin of the macro	r/w	0
F	1:0	DEBUG_MODE	Control the RESETN signal by Firmware when RESETN_FW_SEL is set $0x0$ — The controller FSM drives the efuse signals $0x1$ — The FW controls the efuse signals through the xxx_FW register fields $0x2$ — External pins controls the efuse signals	r/w	0

EFU	0×5001	10810										
	Debug eFUSE data. The data are directly the outputs of the fuse macro											
31 36	31 30 29 28 27 26 25 24 23 22 21 20 19 18 17 16 15 14 13 12 11 10 9 8 7 6 5 4 3 2 1											
			А									
# Bit(s) Field Description												
Α	ro	0										

17.15 LINWICA

LIN wakeUp interrupt controller

	LIN	WICA		IR	Q															0×.	5001	.090	0
					keup interrupts ntains the the enable, clear	, si	tatus	an	d activ	e fla	g for t	he V	Vakeı	up in	terrı	ıpt so	ource	·S.					
31 30	29 28	27 26	25	24	23 22 21 20 19 18	3	17 1	16	15 14	4 1	3 12	11	10	9	8	7	6	5	4	3	2	1	0
			Α	В			С	D						Ε	F							G	Н
#	Bit(s)	Field			Description															Ту	pe	Re	set
Α	25	LIN2			LIN2 wakeup interrupt act	IN2 wakeup interrupt active									r	0	0						
В	24	LIN1			LIN1 wakeup interrupt act	tiv	e													r	0	(9
С	17	LIN2			LIN2 wakeup interrupt sta	atu	IS													r	0	(9
D	16	LIN1			LIN1 wakeup interrupt sta	atu	IS													r	0	(9
E	9	LIN2			LIN2 wakeup interrupt cle — cleared automatically aft			wri	te											٧	VO	(9
F	8	LIN1			LIN1 wakeup interrupt cle — cleared automatically aft			wri	te											٧	VO	(9
G	1	LIN2			LIN2 wakeup interrupt en	ab	le													r	/W	(9
Н	0	LIN1			LIN1 wakeup interrupt en	ab	le													r	/W	(9

17.16 PWM

Pulse width modulation waveform generator

		PWM	BASE	0×5001	L0A00
			Base functions		
31 30	29 28	27 26 25	24 23 22 21 20 19 18 17 16 15 14 13 12 11 10 9 8 7 6 5 4	3 2	1 0
					Α
#	Bit(s)	Field	Description	Туре	Reset
A	1:0	PRESCALES	Prescaler select Defines the ratio between the system clock and the clock used for the waveform generator 0x0 — Divide by 1 0x1 — Divide by 2 0x2 — Divide by 4 0x3 — Divide by 8	r/w	0

																						···	٥	-	•
PWM CTRL												0×50010A04			1										
			PV	/М сс	ontrol																				
31 30	29 28	27 26	25 24	1 23	3 22 2	21 20	9 19	18 17	16	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
			Δ						В								С								D
#	Bit(s)	Field		Des	criptio	n																Тур	ре	Res	et

#	Bit(s)	Field	Description	Туре	Reset
Α	24	UPDATE	Set to trigger consumption of new PULSE parameters (period and pulse width). The flag is automatically cleared by the hardware when the settings are consumed, so reading a high value indicates that an update is still pending	dual	Θ
В	16	INVERT	Set to invert the output waveform	r/w	0
С	8	ENASTS	Enable status Status of enable in the waveform generator	ro	Θ
D	Θ	ENAREQ	Enable request Set to enable the waveform generator	r/w	Θ

PWM	PULSE	0×50010A08	
	PWM pulse setup		
31 30 29 28 27 26	25 24 23 22 21 20 19 18 17 16	15 14 13 12 11 10 9 8 7 6 5 4	3 2 1 0
	А	В	

#	Bit(s)	Field	Description	Туре	Reset
Α	31:16	PERIOD	Specifies the period of the output waveform in terms of a number of prescaler output cycles	r/w	0
В	15:0	PWIDTH	Pulse Width Specifies the pulse width of the output waveform in terms of a number of prescaler output cycles. This control normally determines the high time of the output waverform, however, if INVERT is set it determines the low time	r/w	Θ

	P	WM IN	TEDGECTRL	0×50010A0C						
			M interrupt control tains the PWM edge interrupt sources.							
31 30	29 28 2	27 26 25 2	4 23 22 21 20 19 18 17 16 15 14 13 12 11 10 9 8 7 6 5 4 A	3 2	1 0 B					
#	Bit(s)	Field	Description	Туре	Reset					
Α	17:16	17:16 CLEAR Interrupt clear								
В	1:0	ENABLE	Interrupt enable	r/w	0					

PWM	PWM INTEDGESTATUS										
	PWM interrupt status Contains the the status for the P	WM edg	ge interrupt sources.								
31 30 29 28 27 26	25 24 23 22 21 20 19 18	17 16	15 14 13 12 11 10 9 8 7 6 5 4	3 2	1 0						
		Α			В						

#	Bit(s)	Field	Description	Туре	Reset
Α	17:16	IRQ	Interrupt active Each channel of PWM respresents 2 bits in edge triggered interrupt. LSB representing rising edge interrupt and MSB representing falling edge interrupt	ro	0
В	1:0	STATUS	Interrupt status Each channel of PWM represents 2 bits in edge status. LSB representing rising edge and MSB representing falling edge. Note: 0x2 by default since PWM always triggers the falling edge when PWM starts off disabled	ro	2

	F	PWM	INT	TUPDATED													0×5	5001	0A14	ŀ
				A interrupt control tains the enable, clear,	status and	acti	ive fo	or the P\	WM ı	upda	ted inter	rupt	sourc	es.						
31 30	29 28	27 26	25 24	4 23 22 21 20 19	18 17	16	15	14 13	12	11	10 9	8	7	6	5	4	3	2	1	0
			А	A		В						С								D
#	Bit(s)	Field		Description													Ту	ре	Res	et
Α	24	IRQ		Interrupt active													r	0	0	
В	16	STATUS	S	Interrupt status													r	0	0	
С	8	CLEAR		Interrupt clear													W	0	0	
D	Θ	ENABLI	E	Interrupt enable													r	/W	0	

17.17 I2S

12S Master Transmitter register

		I2S CO	NF																					0×	5001	L0B0	0
		Con	figuration	Regis	er																						
31 30	29 28	27 26 25 24	23 22	21 2	20 1	19 1	.8	17	16	15	14	1	3 1	2	11	10	9	8	8	7	6	5	4	3	2	1	0
		Α				В			С				С)			E						F				G
#	Bit(s)	Field	Descrip	otion																				T	ype	Re	set
А	27:24	BITSTS	12S bits Represe			naini	ng	bits	s to sl	hift															ro	(0
В	19:18	SCKHT	SCK hig Defines		nigh	perio	od	in te	erms	of r	umb	er	of sy	ste	em c	lock	с ре	rioc	ls					r	/W	(0
С	17:16	SCKLT	SCK low Defines		ow I	perio	d i	in te	erms (of n	umbe	er c	of sys	stei	m cl	ock	pei	iod	S					r	/W	(0
D	12	EDGESEL	I2S shift If 0 the slave is	I2S sla	ive i	is exp				-					_	_	ge o	f SC	CK.	lf 1	the	I2S		r	/W	(Θ
Е	11:8	WORDSIZE	12S data Select t			r of b	oits	s to t	trans	mit.	Ex:T	o t	rans	mit	16	bits	set	thi	s to	15				r	/W	0)	xF
F	4	SOURCESEL	source s	select																				r	/W	(0
G	0	ENABLE	I2S stro enable			r tran	sm	nitte	er															r	/W	(0

17.18 UARTA

UART

		UART	A	DA	TA																			0×5	001	0D00)
31 30	29 28	27 26	25 2	24 23	22	21	20]	19	18	17	16	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
	ı																						,	4			
#	Bit(s)	Field		Desc	riptio	on																		Ту	ре	Res	et
Α	7:0	DATA		Used	l for l	both	receiv	/ed	data	a and	d dat	a tha	at is t	o be	e tra	nsmi	tted							du	al	0	

			D	alas	sn	ee	Ĺ -
	UA	RTA UART	DATARECEIVESTATUS	0x5	001	0D04	ļ
		This re	eceive Status gister contains the receive status associated with the current byte read from the UART_ the Data Receive Status register is updated only after a read from the UART_DATA regis the-Read UART_DATA byte first. Then read UART_DATA_RECEIVE_STATUS register sec	ter. <b< th=""><th>_</th><th>ister.</th><th></th></b<>	_	ister.	
31 30	29 28	27 26 25 24	23 22 21 20 19 18 17 16 15 14 13 12 11 10 9 8 7 6 5 4	3	2	1	0
					Α	В	С
#	Bit(s)	Field	Description	Тур	е	Res	et
A	2	BREAKERROR	Break Error This bit is set to 1 if a break condition was detected, indicating that the received data input was held LOW for longer than a full-word transmission time (defined as start, data, parity, and stop bits)	ro)	0	
В	1	PARITYERROR	Parity Error When this bit is set to 1, it indicates that the parity of the received data character does not match the parity selected as defined by bits 2 and 7 of the UARTLCR_H register	ro)	0	
С	Θ	FRAMEERROR	Framing Error When this bit is set to 1, it indicates that the received byte did not have a valid stop bit (a valid stop bit is 1)	ro)	0	

		JARTA	MS	GC	TR	21																					0×1	5001	0D0	98
		,,,,,,,				ontrol																								
					,0 0.					1	1		ı		_								1				ı	1		
31 30	29 28	27 26 25	24 2	23	22			9		17	16	15	14	13	12	1	1	10	9	1	8	7	6	-	5	4	3	2	1	0
			,	A	В	С	D	E	F	(3																	Н	1	J
#	Bit(s)	Field			ı	Descr	iptio	1																			Ту	/pe	Re	eset
Α	23	L00PENA				Loopb Set to				back	<																r,	/W		0
В	22	BREAKENA	A			Break Set to			ansr	nissi	on o	of zer	o (fo	ra	brea	k co	ono	ditio	on)								r,	/W		0
С	21	STICKENA	A			Sticky Set to					rity																r,	/W		0
D	20	PARODD				Odd p Set fo		ра	rity	(see	alsc	PAF	RENA	١)													r,	/W		0
E	19	PARENA				Parity Set to			parit	ty (se	ee P	ARO	DD f	or	odd/	eve	n)										r	/W		0
F	18	STOP			3		⟨ 0 – ⟨ ⟨ 1 –	One	e sto 5-bi	•	nsm	issio	n it s	ele	cts 1	.5 s	itoj	p bi	its, o	othe	erw	ise 2	2 sto	op b	oits		r,	/W		0
G	17:16	SIZE			-	0>	missio (1 – ((2 –) (3 –)	5-b 5-b 7-b	it it it	size																	r,	/W		3
Н	2	UFIF0S0	FTRES	ET	1	FIFO S Reset — clea	s FIF) p	oint						izes	FIF	0 (con	ten	ts to) ZE	ero					W	10		0
I	1	ENABLE_S	STS			Enable Status			T er	nable)																r	0		0
J	0	ENABLE			:	Set to	enab	le '	the I	UAR	Т																r,	/W		0

v1.1 iND83207 B0

																													l	Da	ata	sh	ee	et -
		UA	RT	А	ı	J	ΑF	RTI	ΝT																						0×1	5001	.0D	0C
								T Inte			na	ble, s	tatus	а	ınd clea	ar f	or t	:he l	JAR	tT in	terrı	upt	SOL	ırce	es.									
31 30	29	28	27	26	25	2	24	23	22	21	2	0 19	18		17 16	1	L5	14	13	12	11		10	9	8	7	6	5	Ī	4	3	2	1	0
	Α	В	С	D	Ε		F			G	F	i I	J		K L				М	N	0		Р	Q	R			S		Т	U	٧	W	/ X
#	Bit	(s)	Fie	eld				Desc	ript	ion																					Ту	ре	R	eset
Α	2	29	TX	DON	E							ne Inte I whe			transm	iss	ion	is do	one												r	0		0
В	2	28	BR	EAK	KERI	R		Brea Set b				-	n a b	or	eak err	or	occ	urs													r	0		0
С	2	27	PR	TYE	RR			Parit Set b					n a p	oa	rity err	or	oco	urs													r	0		0
D	2	26	FR	MER	R				-			errup Г whe		ra	aming e	erro	or o	ccur	s												r	0		0
E	2	25	0٧	'RUN	ERR							errup F whe		0	verrun	er	ror	occi	ırs												r	0		0
F	2	24	RX	DON	E							terruμ Γ whe		d	lata is ı	ea	dy														r	0		0
G	2	21	TX	DON	E			Tran					n the	e i	transm	it i	s do	one													r	0		0
Н	2	20	BR	EAK	KERI	R		Brea Set b		-	٩R	Γwhe	n a b	or	eak err	or	occ	urs													r	0		0
1	1	19	PR	TYE	RR			Parit Set b	-		٩R	Γwhe	n a p	oa	rity eri	or	oco	urs													r	0		0
J	1	18	FR	MER	R			Fram Set b	-			Γwhe	n a f	ra	aming e	erro	or o	ccur	s												r	0		0
К	1	.7	0V	RUN	ERR			Over Set b				Γwhe	n an	0	verrun	er	ror	occi	ırs												r	0		0
L	1	L 6	RX	DON	E			Rx D Set b				Γwhe	n Rx	d	lata is ı	ea	dy														r	0		0
М	1	13	TX	DON	E							ne Inte atical			Clear r each v	vrit	te														W	0		0
N	1	12	BR	EAK	KERI	R						rupt (atical		eı	r each v	vrit	te														W	0		0
0	1	.1	PR	TYE	RR							rupt (atical		ei	r each v	vrit	te														W	0		0
Р	1	LO	FR	MER	R							errup atical			r each v	vrit	te														W	0		0
Q		9	0V	RUN	ERR							errup atical			r each v	vrit	te														W	0		0
R		8	RX	DON	E							terru _l atical			r r each v	vrit	te														W	0		0
S		5	TX	DON	E			Tran	smis	sion	doı	ne Inte	errup	t I	Enable																r,	/W		0
Т		4	BR	EAK	KERI	R		Brea	k Err	or In	ter	rupt E	nabl	e																	r,	/W		0
U		3	PR	TYE	RR			Parit	y Err	or In	ter	rupt E	nabl	e																	r,	/w		0

Framing error Interrupt Enable

Overrun error Interrupt Enable

Rx Data ready Interrupt Enable

FRMERR

RXDONE

OVRUNERR

W

Χ

r/w

r/w

r/w

0

0

0

																										ala		CC	٠.
		UAI	RTA	ι	JAR	TBA	UD																			0×!	5001	.0D2	0
				T b	The c	Baud contro rate i	ols in is giv	this en b	y th	ne fo	llow	ing e	equa	tion.	bau	d_rat	e =	Fclk/	(OSI	R*(B/	٩UD	DIV+	+1)) v					The	
31 3	30 29	28	27 26	25	24	23	22	21	20	19	18	17	16	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
		Α			В						С											D							
#	В	it(s)	Field			Des	crip	tion																		Ту	/pe	Res	set
Α		28	URET	ARD				egist		ple v	vinde	ow b	y 1 o	cycle	. For	Del	oug									r,	/W	0)
В		24	UADV	ANCI	E			Regi			e win	ndow	/ by :	1 сус	cle. F	or D	ebu	g								r	/W	0)
С	20	:16	0SR					nplin SR Ra	_		to 16	5														r	/W	0×	10
D	1	5:0	BAUD	DIV		Bau	d rat	e div	ider																	r,	/W	0)

17.19 GPIOA

ASIC GPIO registers

		GPIOA G	PADATA	0×5001	L4000
		G	PIO Port A Data		
31 30	29 28	27 26 25 24	23 22 21 20 19 18 17 16 15 14 13 12 11 10 9 8 7 6 5	4 3 2	1 0
				А	
#	Bit(s)	Field	Description	Туре	Reset
A	4:0	GPADATA<1024	Port A data Data written to or read from Port A Note: the address shown is the base address for access. The memory space actually covers 1024 bytes. The 8 bits of data written/read are masked by bits 9: of the address used. This allows access of specifically enabled bits in the data field. For direct access of the full GPIO port, the address of the port, must be incremented by 0x3FC. This has the effect of setting address[9:0] to 0b11111111 00 which enables read and write access of all bits in the port.	dual	0

		GPIOA G	PBDATA	0×500	14400
		G	PIO Port B Data		
31 30	29 28	27 26 25 24	23 22 21 20 19 18 17 16 15 14 13 12 11 10 9 8 7 6 5 4	3 2	1 0
	1				Α
#	Bit(s)	Field	Description	Туре	Reset
Α	2:0	GPBDATA<1024	> Port B data	dual	0



		GPIOA	GPENA	0×:	5001	4C0	0
			GPIO Port Enables				
31 30	29 28	27 26 25	24 23 22 21 20 19 18 17 16 15 14 13 12 11 10 9 8 7 6 5 4	3	2	1	0
					Α	В	С
#	Bit(s)	Field	Description	Ту	ре	Re	set
Α	2	GPLENA	GPL Enable	r,	/w	1	L
В	1	GPBENA	GPB Enable	r,	/w	1	L
С	0	GPAENA	GPA Enable	r,	/w	1	L

																											U	alc	เรา	ee	ι -
		G	PIC	Α		G	PA	PL																				0×	5001	4C0	4
						G	PIO	Poi	t A I	Lov	ver Nil	oble I	Pins (Con	trol																
31 30	29	28	27	26	2	5 2	4	23	22	2	1 20	19	18	17	16	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
	Α	В	С	D	E	E	F			C	6 Н	1	J	К	L			М	N	0	Р	Q	R			S	Т	U	٧	W	Х
#	Bit	(s)	Fie	ld					Desc	rip	tion																	T	ype	Res	set
Α	2	29	GP	AAC	TD	ET[:	3]	F	Pin 3	ac	tivity i	nterr	upt																ro	n/	'a
В	2	28	GP	ACLI	R[3]					terrupi ed aut			⁄ aft	ter ea	ch wi	rite											٧	٧O	6)
С	2	27	GP	AFE	[3]		F	Pin 3	fa	lling ed	lge e	nable	2														r	/W	()
D	2	26	GP	ARE	[3]		F	Pin 3	ris	ing ed	ge en	able															r	/W	0)
Е	2	25	GP	AIE	[3]		F	Pin 3	in	terrupi	mas	k															r	/W	6)
F	2	24	GP	ADII	R[3]		F	Pin 3	οι	ıtput e	nable	?															r	/W	6)
G	2	21	GP	AAC	TD	ET[2]	F	Pin 2	ac	tivity i	nterr	upt															1	ro	n/	'a
Н	2	20	GP	ACLI	R[2]					terrupi ed auto			⁄ aft	ter ea	ch wi	rite											١	VO	0)
I	:	19	GP	AFE	[2]		F	Pin 2	fa	lling ed	lge e	nable	2														r	/W	6)
J	1	18	GP	ARE	[2]		F	Pin 2	ris	ing ed	ge en	able															r	/W	0)
K	:	17	GP	AIE	[2]		F	Pin 2	in	terrupi	mas	k															r	/W	6)
L	:	16	GP	ADI	R[2]		F	Pin 2	οι	ıtput e	nable	?															r	/W	6)
М	:	13	GP	AAC	TD	ET[1]	F	Pin 1	ac	tivity i	nterr	upt															1	ro	n/	a
N	-	12	GP	ACLI	R[1]					terrupi ed auto			⁄ aft	ter ea	ch wi	rite											١	VO	6)
0		11	GP	AFE	[1]		F	Pin 1	fa	lling ed	lge e	nable	2														r	/W	(-)
Р	1	10	GP	ARE	[1]		F	Pin 1	ris	ing ed	ge en	able															r	/W	0)
Q		9	GP	AIE	[1]		F	Pin 1	in	terrupi	mas	k															r	/W	0)
R		8	GP	ADII	R[1]		F	Pin 1	οι	ıtput e	nable	?															r	/W	6)
S		5	GP	AAC	TD	ET[0]	F	Pin 0	ac	tivity i	nterr	upt															-	ro	n/	'a
Т		4	GP	ACLI	R[0]					terrupi ed auto			⁄ aft	ter ea	ch wi	rite											٧	VO	0)

	G	PIOA GPA	NPU			0×5	5001	4C08	3
		GPIC	Port A Upper Nibble Pins Control						
31 30	29 28	27 26 25 24	23 22 21 20 19 18 17 16 15 14 13 12 11 10 9 8 7 6	5	4	3	2	1	0
				Α	В	С	D	Е	F
#	Bit(s)	Field	Description			Ту	ре	Res	et
Α	5	GPAACTDET[4]	Pin 4 activity interrupt			r	0	n/	а
В	4	GPACLR[4]	Pin 4 interrupt clear — cleared automatically after each write			W	10	0	
С	3	GPAFE[4]	Pin 4 falling edge enable			r,	/w	0	
D	2	GPARE[4]	Pin 4 rising edge enable			r,	/w	0	
Е	1	GPAIE[4]	Pin 4 interrupt mask			r,	/w	0	
F	0	GPADIR[4]	Pin 4 output enable			r,	/w	0	

U

W

Χ

3 GPAFE[0]

GPARE[0]

GPAIE[0]

GPADIR[0]

Pin 0 falling edge enable

Pin 0 rising edge enable

Pin 0 interrupt mask

Pin 0 output enable

r/w

r/w

r/w

0

0

0



#	Bit(s)	Field	Description	Туре	Reset
Α	21	GPBACTDET[2]	Pin 2 activity interrupt	ro	n/a
В	20	GPBCLR[2]	Pin 2 interrupt clear — cleared automatically after each write	WO	0
С	19	GPBFE[2]	Pin 2 falling edge enable	r/w	0
D	18	GPBRE[2]	Pin 2 rising edge enable	r/w	0
Е	17	GPBIE[2]	Pin 2 interrupt mask	r/w	0
F	16	GPBDIR[2]	Pin 2 output enable	r/w	0
G	13	GPBACTDET[1]	Pin 1 activity interrupt	ro	n/a
Н	12	GPBCLR[1]	Pin 1 interrupt clear — cleared automatically after each write	WO	0
ı	11	GPBFE[1]	Pin 1 falling edge enable	r/w	0
J	10	GPBRE[1]	Pin 1 rising edge enable	r/w	0
K	9	GPBIE[1]	Pin 1 interrupt mask	r/w	0
L	8	GPBDIR[1]	Pin 1 output enable	r/w	0
М	5	GPBACTDET[0]	Pin 0 activity interrupt	ro	n/a
N	4	GPBCLR[0]	Pin 0 interrupt clear — cleared automatically after each write	WO	0
0	3	GPBFE[0]	Pin 0 falling edge enable	r/w	0
Р	2	GPBRE[0]	Pin 0 rising edge enable	r/w	0
Q	1	GPBIE[0]	Pin 0 interrupt mask	r/w	0
R	0	GPBDIR[0]	Pin 0 output enable	r/w	0

	G	PIOA		G	PLP	L																			0×!	5001	.4C14	4
				G	SPIO P	ort L	IN I	Pin Co	ntrol																			
31 30	29 28	27 26	2	5 2	24 23	3 22	2 2	21 26	19	18	17	16	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
															Α	В	С	D	Ε	F			G	Н	1	J	K	L
#	Bit(s)	Field				Des	cri	otion																	Ту	/ре	Res	set
Α	13	GPLAC	TD	ET[1]	LIN2	2 ac	tivity	interr	upt															r	0	n/	'a
В	12	GPLCL	.R[1]				terrup ed au			y aft	ter ead	ch wi	rite											W	10	0)
С	11	GPLFE	[1]		LIN2	2 fa	lling e	dge e	nable	2														r,	/W	0)
D	10	GPLRE	[1]		LIN2	2 ris	sing ed	lge en	able															r,	/W	0)
E	9	GPLIE	[1]		LIN2	2 in	terrup	t mas	k															r,	/W	0)
F	8	GPLDI	R[1]		LIN2	2 οι	ıtput (enable	?															r,	/W	0)
G	5	GPLAC	TD	ET[0]	LIN	1 ac	tivity	interr	upt															r	0	n/	'a
Н	4	GPLCL	.R[0]				terrup ed au			y aft	ter ead	ch wi	rite											W	10	0)
ı	3	GPLFE	[0]		LIN	1 fa	lling e	dge e	nable	2														r,	/W	0)
J	2	GPLRE	[0]		LIN	1 ris	sing ed	lge en	able															r,	/W	0)
К	1	GPLIE	[0]		LIN	1 in	terrup	t mas	k															r,	/W	0)
L	Θ	GPLDI	R[0]		LIN	1 οι	ıtput e	enable	2															r,	/W	0)

17.20 TIMER0

		TIMER0	COUNT	0x5002	20000
			Timer Counter Register		
31 30	29 28	27 26 25 2	24 23 22 21 20 19 18 17 16 15 14 13 12 11 10 9 8 7 6 5 4	3 2	1 0
			Α		
#	Bit(s)	Field	Description	Туре	Reset

		TIMER0	CFG	0×5002	20004
			Timer Control Register		
31 30	29 28	27 26 25 2	24 23 22 21 20 19 18 17 16 15 14 13 12 11 10 9 8 7 6 5 4	3 2	1 0 A
#	Bit(s)	Field	Description	Туре	Reset
Α	0	ENA	Enable This bit starts/stops the timer: < br> 1 = Timer Running < br> 0 = Timer Inactive	r/w	0

17.21 TIMER1

		TIMER1	COUNT	0×500	20008
			Timer Counter Register		
31 36	29 28	27 26 25 2	24 23 22 21 20 19 18 17 16 15 14 13 12 11 10 9 8 7 6 5 4	3 2	1 0
			Α		
#	Bit(s)	Field	Description	Туре	Reset
Α	31:0	COUNT	Initial counter value. The timer will count from this value to 0xFFFFFFFF and roll over to 0x00000000. At this point it will generate an interrupt if enabled. The interrupt routine is responsible for reloading the value if needed as this timer does not auto-reload the	r/w	Θ

		TIMER1	CFG	0×500	2000C
			Timer Control Register		
31 30	29 28	27 26 25 2	24 23 22 21 20 19 18 17 16 15 14 13 12 11 10 9 8 7 6 5 4	3 2	1 0
					А
#	Bit(s)	Field	Description	Туре	Reset

17.22 TIMER2

		TIMER2	COUNT	0×500	20010
			Timer Counter Register		
31 30	29 28	27 26 25 2	24 23 22 21 20 19 18 17 16 15 14 13 12 11 10 9 8 7 6 5 4	3 2	1 0
			Α		
#	Bit(s)	Field	Description	Туре	Reset

		TIMER2	CFG	0×5002	20014
			Timer Control Register		
31 30	29 28	27 26 25 2	24 23 22 21 20 19 18 17 16 15 14 13 12 11 10 9 8 7 6 5 4	3 2	1 0
					Α
#	Bit(s)	Field	Description	Туре	Reset
A	0	ENA	Enable This bit starts/stops the timer: < br> 1 = Timer Running < br> 0 = Timer Inactive	r/w	0

17.23 WDT1

Watchdog timer

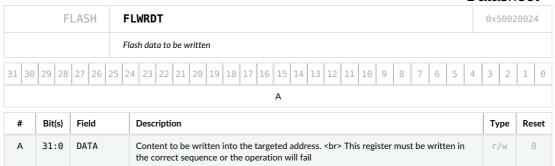
WDT1	CFG	0×5	5002	0018	8
	Config				
31 30 29 28 27 26 25	24 23 22 21 20 19 18 17 16 15 14 13 12 11 10 9 8 7 6 5	4 3	2	1	0
		Α	В	С	D

#	Bit(s)	Field	Description	Туре	Reset
A	4:3	PRESET	Defines the watchdog timeout period. 	r/w	0
В	2	RSTFLAG	Reset flag This flag is set by the system at the initialization if the initialization was caused by a reset triggered by the WDT. The bit can be cleared by the application	r/w	0
С	1	RSTEN	Reset enable If enabled a WDT time-out will force the microcontroller to reset. This bit can be asserted but it cannot be de-asserted	r/w	0
D	0	ENA	WDT Enable This bit can be asserted but it cannot be de-asserted. It means that once the WDT is enabled it cannot be turned off until a Reset or Power-On Reset occurs	r/w	Θ

	W	DT1	KEY	0×5002	:001C
			Writing the sequence KEY0, KEY1 to this register will clear (pet) the watchdog - preventing it fr and resetting the system.	rom timin	g out
31 30	29 28	27 26	25 24 23 22 21 20 19 18 17 16 15 14 13 12 11 10 9 8 7 6 5 4	3 2	1 0
			Α		
#	Bit(s)	Field	Description	Туре	Reset
Α	31:0	KEY	To clear the WDT counting the following words must be written in this order and without any other instruction between then: KEY0: 0x3C570001. KEY1: 0x007F4AD6	r/w	Θ

17.24 FLASH

	F	LASH	FLADDR	0×50	020020
			Destination address for flash write / erase operation		
31 30	29 28	27 26 25	24 23 22 21 20 19 18 17 16 15 14 13 12 11 10 9 8 7 6 5	4 3	2 1 0
			Α		
#	Bit(s)	Field	Description	Туре	Reset
Α	16:0	ADDR	Target address for write/erase operation. In byte writes, this is the read address of the flash to be written to. In erase modes, it is a read address inside the sector to be erased. This register must be written in the correct sequence or the	r/w	0xFFFF



	FLASH UNLBWR												
	Flash data unlock register												
31 30	31 30 29 28 27 26 25 24 23 22 21 20 19 18 17 16 15 14 13 12 11 10 9 8 7 6 5 4 3 2 1												
#	Bit(s)	Field		Description	Туре	Reset							
Α	·												

	FLASH BWRSTRT													
	Flash write start register													
31 30	31 30 29 28 27 26 25 24 23 22 21 20 19 18 17 16 15 14 13 12 11 10 9 8 7 6 5 4 3 2 1													
	I	I		, , , , , , , , , , , , , , , , , , ,	1									
#	Bit(s)	Field		Description	Туре	Reset								
A 31:0 WRITE_START Control register to start a write. A value of 0xAAAAAAA must be written to this address at the correct point in the write sequence or the operation will fail														

	FLASH UNLSER											
	Flash sector erase unlock register											
31 30	31 30 29 28 27 26 25 24 23 22 21 20 19 18 17 16 15 14 13 12 11 10 9 8 7 6 5 4 3 2 1 0 A											
#	Bit(s)	Field		Description	Туре	Reset						
Α	A 31:0 UNLOCK_ERASE Control register to unlock a sector erase. A value of 0x66666666 must be written to this address at the correct point in the sector erase sequence or the operation will fail											

	F	LASH	SER	STRT	0x50020034									
	Flash sector erase start register													
31 36	31 30 29 28 27 26 25 24 23 22 21 20 19 18 17 16 15 14 13 12 11 10 9 8 7 6 5 4													
				A										
#	Bit(s)	Field		Description	Туре	Reset								
A 31:0 ERASE_START Control register to commit a sector erase. A value of 0x99999999 must be written to this address at the correct point in the sector erase sequence or the operation will fail														

				occo.	.00								
	FLASH FLSCTRL												
			Flash control register										
31 30	29 28	27 26 2	5 24 23 22 21 20 19 18 17 16 15 14 13 12 11 10 9 8 7 6 5 4	3 2	1 0 A								
#	Bit(s)	Field	Description	Туре	Reset								
Α	A 1:0 CTRL Number of wait states used in the reading process. Each read from flash memory will take number of cycles equal to 1+RWC to complete												

	FLASH FLSCP 02												
			Flash code protection register										
31 30	29 28	27 26 25	24 23 22 21 20 19 18 17 16 15 14 13 12 11 10 9 8 7 6 5 4	3 2	1	0							
Α													
#	Bit(s)	Field	Description										
A	31:0	CODE_PRO	Code Protection / SerialWire Lockout Control SerialWire a value of 0xF2E11047 to disable the SerialWire interface. Note: A value of 0xF2E11047 to disable the SerialWire interface. Note: A value of 0xF2E11047 to disable the SerialWire interface. Note: A value of 0xF2E11047 to disable the SerialWire interface to prevent unauthorized debug access to the part. Note: Note: Note: This register does not lock the Flash Memory against read/write/erase by the applications program. Instead what it does is to disable all communications with the debug interface, therefore preventing any external attack. The application code is still able to modify the flash content. Note: Upon Power-On Reset or Normal Reset the system disables the communication for a small time interval (8192 clock cycles). If the application needs to be protected it is mandatory to set this register with the appropriate code in the beginning of the initialization process and before the internal hardware enable the debug communication	r/w	()							

	F	LASH	FLS_U	INLOC	K_CTRL	_OP											0x50020050				
	Flash Unlock Control Operation Register																				
31 30	1 30 29 28 27 26 25 24 23 22 21 20 19 18 17 16 15 14 13 12 11 10 9 8 7 6 5 4												3	2	1	0					
	A																				
#	Bit(s)	Field		Desc	ription												Ту	ре	Res	set	
Α	31:0	UNLOCK_	_CTRL_OP	OxAC Oper lock: Regis Regis writte of the	DC_1972 ation Reg 0: TI ter (FLAS ter is unlo en. Ne lock is cl	peration R needs to ister acces ne Contro H_CTRL_cocked. The locked. The lote: Afte leared and	be wri ss. Wh l Opers DP) can Contr each the pa	tten in en this ation R nnot be ol Ope write t	this reg registe legister writte eration I o the F	r is re is locl n. <br Regist LASH</br 	ad, it ked. ¹ r> 1: ⁻ ter (FI _CTR	retur The C The C LASH L_OP	ns the ontro ontro _CTRI regis	state l Ope l Ope OP ter, th	e of to ration ration can ne sta	n n be ate	r	/w	6)	

	F	LASH	CTRL_OP	0×50	9020	9054
			Flash Control Operation Register			
1 36	29 28	27 26	25 24 23 22 21 20 19 18 17 16 15 14 13 12 11 10 9 8 7 6 5 4	3	2	1 0
					A	. Е
#	Bit(s)	Field	Description	Тур	е	Rese
# A	Bit(s) 2:1	Field SIZE	Description SIZE of the write operation Refer to data sheet for more information of the use of this field	Typ		Reset

		FLASH	Т	RIN	1																			0×50020058			}
			FI	lash T	Trim	Regi	ister																				
31 30	31 30 29 28 27 26 25 24 23 22 21 20 19 18 17 16 15 14 13 12 11 10 9 8 7 6 5 4											3	2	1	0												
	A B C																										
#	# Bit(s) Field Description											Ту	ре	Res	et												
А	17	SLEEPDEER	P_CF(G	T se	his r ector oing	egis r 1 (awa	@00	vill b 01_0 ıring	e au 0000 Dee	toma). W	atical hen	lly po set, t	the s	yste	m w	ill NC	DT be	e res	et if '	n the VDD eset i	_IO i		r/	/W	0	
В	16	SDIO_TIM	ING_(CFG	Ti se ri:	SDIO interface timing configuration This register will be automatically populated with the value stored in the NVR sector 1 (@0001_0000). When set, the SDIO/INT signals are captured on the rising edge of CLK. When cleared, these data are captured on the falling edge of CLK											r/	/W	1								
С	15:0	OSC_TRIM	RIM Oscillator Trim Value This register will be automatically populated with the value stored in the NVR sector 1 (@0001_0000)										r/	/W	8x0	36											

18 Interrupts

There are 22 interrupt channels - 16 used by the ASIC die and 6 used by the Verne MCU..

Interrupt #	Interrupt name	Block	Comment
0	FrequencyCounterFIFO_IRQn	US_TRX	
1	Brownout_IRQn	CRGA	Brown-out detect / reset
2	Watchdog_A_IRQn	WDT	Watchdog timer interrupt
3	GPIO_IRQn	GPIO	
4	EnvelopeFIFO_IRQn	US_TRX	
5	LIN_Master_IRQn	LIN	LIN Master
6	LIN_Wakeup_IRQn	LIN	Wakeup from LIN message
7	LIN_Slave_IRQn	LIN	LIN Slave
8	PWM_0_IRQn	PWM	
9	LINDLYCOMP_IRQn	LIN	
10	USTRXError_IRQn	US_TRX	
11	USTRXStatus_IRQn	US_TRX	
12	UART_A_IRQn	UART	ASIC UART interrupt
13	ADC_A_IRQn	ADC_CTRL	
14	ClockCal_IRQn	CCAL	
15	Lullaby_IRQn		Indicates when the ASIC can safely enter hibernate mode
16	Timer0_IRQn	TMR_0	MCU Timer 0
17	Timer1_IRQn	TMR_1	MCU Timer 1
18	Timer2_IRQn	TMR_2	MCU Timer 2
19	Watchdog_IRQn	WDT	
20	BTE_IRQn	ВТЕ	Block Transfer Engine
21	SDIO_IRQn		Serial Data IO

18.1 Interrupt support on GPIOs

Interrupts are generated based on the transitional value of a pin (e.g. button press). At power-on reset, the GPA lines are HighZ and the GPB lines default to inputs.

The GPIO interrupts are synchronous to the system clock (clk_sys).

18.1.1 GPIO Interrupt Handling

The iND83207 GPIO shares a single hardware interrupt for all 3 GPIO ports (A, B & L). To ensure that there is no possibility of missing an interrupt request from any of the ports that occurs whilst you are handling a request from the GPIO, it is best practise to continue to record and clear flags that are set in the individual interrupt status registers (for each interrupt-enabled bit of each GPIO port) until a value of zero is read back from all of them.

The following code implements the start of a GPIO irq handler that uses such an approach.

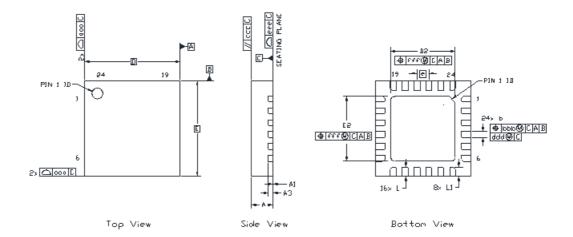
```
#define GPIOA_ACT_DET_FLAG_mask 0x20202020
#define GPIOA_ACT_DET_FLAG_TO_CLEAR_rshft 1
#define N_GPIO_FLAG_BYTES 4
void GPIO Handler (void)
    // to avoid any possibility that a newly detected edge that we don't handle during this
call of the
    // GPIO interrupt handler (e.g. one that is detected at any point during the execution
of the handler)
    // we need to make sure that all the individual interrupt request lines (from each
interrupt-enabled,
    // bit of each GPIO port) are clear (thus any new edge will lead to a positive edge on
the overall
    // request line and therefore a new interrupt event at the input to the NVIC)
    // we do this by starting the handler with a short piece of code that records (and
clears) all the
    // asserted edge detection flags of the GPIO peripheral - continuing to do so until it
has observed
    // no new flags on any port since it last cleared a flag...
    uint32_t all_flags_found = 0; // a variable in which we build up a record of all the
SFR 'activity detec(ed)
    // flags that we find, all bits for all three ports will end up in this register -
laid out as follows...
   // 31 30 29 28 27 26 25 24 23 22 21 20 19 18 17 16 15 14 13 12 11 10 9 8 7 6 5
4 3 2 1 0
A4 A3 A2 A1 A0
    uint32_t flags_etc; // temporary storage for the contents of a GPIO ctrl/status word
    uint32_t new_flags; // a record of any new flags read from the current byte we are
    uint32_t *p_flags; // a pointer to the relevant SFR control/status byte
    uint8_t i_flag_word = 0; // which of the SFR words we are currently processing
    int8_t leftshift; // a shift used to align the least significant SFR flag with 'all
flags found
    uint32_t found_flag_nibble_mask; // a mask used when copying flags into 'all flags
   uint8_t reads_since_new_flag = 0; // how many times we have read flag SFR bytes since
finding any flags
    uint8_t i_bit, n_bits;
    const uint8_t n_bits_per_word[] = {4, 1, 3, 2}; // the number of GPIO bit controlled by
each SFR word
    while (reads_since_new_flag < N_GPIO_FLAG_BYTES) {</pre>
      // set up some variables that are dependent on the loop counter (which SFR byte we
are dealing with)..
     p_flags = (volatile uint32_t *)(0x50014C04 + ((i_flag_word == 3)?
16:(4*i_flag_word)));
     leftshift = (i_flag_word * 4) - 5; // word->nibble bit_count minus the shift required
for the first flag
     n_bits = n_bits_per_word[i_flag_word]; // the number of bits in the GPIO port (8 in
'A', 4 in 'B' & 'L'
     found_flag_nibble_mask = 0x0F << (4 * i_flag_word); // isolates bits of the</pre>
appropriate nibble for this byte
```

```
// start by checking for any new 'activity detect(ed)' flags in this peripheral
control/status SFR byte
     // (keeping a copy of the entire word so that we can avoid a read-modify-write when
we write to it later).
     flags_etc = *p_flags;
     new_flags = flags_etc & GPIOA_ACT_DET_FLAG_mask;
     while (new_flags) {
       // we found 'new' flags so we need to zero our run length 'without finding new
flags' counter
       reads since new flag = 0;
        // and clear all the new flags that we found in the peripheral control/status
        *p_flags = flags_etc | (new_flags >> GPIOA_ACT_DET_FLAG_TO_CLEAR_rshft);
        // we now loop over the individual flags of this byte, recording which ones we have
found...
        new_flags = (leftshift > 0)? (new_flags << leftshift) : (new_flags >> leftshift); //
moves the least significant new flag to the appropriate bit position in the overall flags
register
        for (i_bit=0; i_bit<n_bits; i_bit++) {</pre>
          all_flags_found \mid= new_flags & found_flag_nibble_mask; // record the new flag
         new_flags >>= 7; // moves the next most significant flag to the appropriate bit
position for the 'all flags' variable
         if (new_flags == 0) break; // no need to continue if there are no flags left
        // re-read the SFR to see if any new flags have been set (since we cleared it)...
        flags_etc = *p_flags;
       new_flags = flags_etc & GPIOA_ACT_DET_FLAG_mask;
     reads_since_new_flag++; // we only bypass or leave the loop when we read 'no new
     if (++i_flag_word >= N_GPIO_FLAG_BYTES) i_flag_word = 0; // increment the flag word
counter
 }
}
```

19 Package Drawing

QFN 4x4 24pins (0.5mm pitch)

Package Outline Drawing



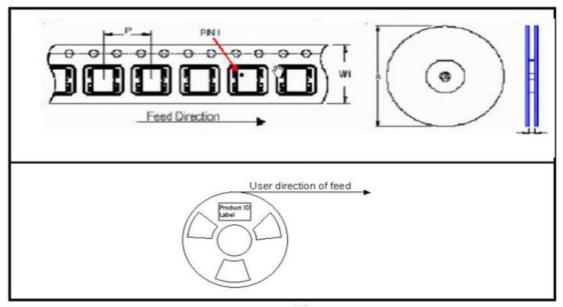
Dimensions and Tolerances

DESCRIPTION		SYMBOL	MIN	NOM	MAX			
total thickness		Α	0.8	0.9	1.0			
stand-off		A1	0.00 0.02 0.05					
L/F thickness		A3		.203 REF				
lead width		b	0.18	0.25	0.30			
hodycizo	Х	D		4.0 BSC				
body size	Υ	E		4.0 BSC				
lead pitch		e	0.5 BSC					
EP size	Х	D2	2.50	2.65	2.80			
EF SIZE	Υ	E2	2.50	2.65	2.80			
lood longth		L	0.30	0.40	0.45			
lead length		L1	0.30	0.40	0.45			
package edge tolerance		aaa		0.15				
lead array offset		bbb		0.10				
mold flatness	ccc		0.10					
lead offset	ddd	0.05						
lead coplanarity		eee	0.08					
exposed pad offset		fff	0.10					

Notes:

- Controlling dimensions are in mm
- Dimensioning and tolerancing per ASME Y14.5M
- This drawing conforms to JEDEC outline MO-220, variation VGGD-6 with exception of feature L, L1 which are per supplier designation.

19.1 Tape & Reel packaging



Device orientation in Tape & Reel packaging

20 Environmental

All indie Semiconductor devices meet the proposed RoHS components for cadmium, mercury, hexavalent chromium, polybrominated biphenyls (PBBs), and polybrominated diphenyl ethers (PBDEs). The composition of indie Semiconductor devices do not contain halogens (including bromine) and inorganic (red) phosphorous as an alternative flame-retardant system.

21 Qualification

Product qualification is performed according to the automotive standard AEC-Q100 described in QM NO. 07PL0254

22 References

Indie semiconductor ARM CORTEX M0 core programming guide.

23 Contacts

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24 Appendix 1: Errata

24.1 LIN Compliance

The LIN master in iND83207 fails to meet the following parts of the LIN Specification Package (Revision 2.2A):

- Param 21 VSerDiode should have a voltage drop at the serial diodes of
 - 0.4V min; 0.7V typ; 1.0V max
 - iND83207 has diode functionality with a typical voltage drop of 1.6V
- Param 25 Rmaster should have a resistance of
 - 900 Ohm min; 1000 Ohm typ; 1100 Ohm max
 - iND83207 has a typical resistance which meets the spec
 - Over process & temperature the spread will be wider than the specified range

When operating as a LIN slave, iND83207 is fully compliant with the LIN Specification Package (Revision 2.2A).

Document history

This document was generated on Monday 31 January 2022 at 08:40 AM (GMT).